

Mighty Gecko Wireless SoC EFR32MG1X232 Data Sheet

The Mighty Gecko family of wireless solutions combines an energy-friendly MCU with a highly integrated radio transceiver supporting Bluetooth Smart®, wireless mesh, and proprietary short range wireless protocols.

The IoT System-On-Chip provides industry-leading energy efficiency, ultra-fast wakeup times, a scalable power amplifier, an integrated balun and no-compromise MCU features.

Mighty Gecko applications include

- Connected Home
- Lighting
- Sports and Fitness
- Metering
- Building Automation

EY FEATURES

- 32-bit ARM® Cortex®-M4 core with 40 MHz maximum operating frequency
- Low energy active and sleep currents
- Scalable Memory and Radio configuration options available in several footprint compatible QFN packages
- 12-channel Peripheral Reflex System enabling autonomous interaction of MCU peripherals
- Autonomous Hardware Crypto Accelerator and True Random Number Generator



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This information applies to a product under development. Its characteristics and specifications are subject to change without notice. Silicon Laboratories Confidential. Information contained herein is covered under non-disclosure agreement (NDA).

1. Features

- Low Power Wireless System-on-Chip.
 - High Performance 32-bit 40 MHz ARM Cortex-M4 with DSP instruction and floating-point unit for efficient signal processing
 - Up to 256 kB flash program memory
 - Up to 32 kB RAM data memory
 - · 2.4 GHz radio operation
 - TX power up to 19.5 dBm
- Low Energy Consumption
 - 8.6 mA RX current at 2.4 GHz (1 Mbps GFSK)
 - 9.1 mA RX current at 2.4 GHz (250 kbps O-QPSK DSSS)
 - 8.2 mA TX current @ 0 dBm output power at 2.4 GHz
 - 60 µA/MHz in Energy Mode 0 (EM0)
 - 1.35 µA EM2 DeepSleep current (full RAM retention and RTCC running from LFXO)
 - 1 µA EM3 Stop current (State/RAM retention)
 - Wake on Radio with signal strength detection, preamble pattern detection, frame detection and timeout
- High Receiver Performance
 - -94 dBm sensitivity at 1 Mbps GFSK
 - -99.4 dBm sensitivity at 250 kbps O-QPSK DSSS
- Modulation Format(s) Supported
 - 2-FSK / 4-FSK with fully configurable shaping
 - Shaped OQPSK / (G)MSK
- Supported Protocol(s)
 - Bluetooth Smart
 - ZigBee®
 - Thread
 - 2.4 GHz Proprietary Protocols

- Wide selection of MCU peripherals
 - 12-bit 1 Msamples/s SAR Analog to Digital Converter
 - 2× Analog Comparator
 - Digital to Analog Current Converter (IDAC)
 - Up to 31 pins connected to analog channels (APORT) shared between Analog Comparators, ADC, and IDAC
 - 31 General Purpose I/O pins with output state retention and asynchronous interrupts
 - 8 Channel DMA Controller
 - 12 Channel Peripheral Reflex System (PRS)
 - Hardware Crypto Acceleration with public key support
 - 2×16-bit Timer/Counter
 - 3 + 4 Compare/Capture/PWM channels
 - 32-bit Real Time Counter and Calendar
 - 16-bit Low Energy Timer for waveform generation
 - 32-bit Ultra Low Energy Timer/Counter for periodic wakeup from any Energy Mode
 - 16-bit Pulse Counter with asynchronous operation
 - Watchdog Timer with dedicated RC oscillator @ 50 nA
 - 2×Universal Synchronous/Asynchronous Receiver/Transmitter (UART/SPI/SmartCard (ISO 7816)/IrDA/I²S)
 - Low Energy UART (LEUARTTM)
 - I²C interface with SMBus support and address recognition in EM3 Stop

Wide Operating Range

- 1.62 V to 3.8 V single power supply
- -40 °C to 85 °C
- QFN48 7x7 mm Package

2. Ordering Information

Ordering Code	Frequency Band	Core	Flash (kB)	RAM (kB)	Protocol Stack	Encryption	Max TX Power (dBm)
EFR32MG1P232F256GM48-A0	2.4 GHz	M4	256	32	 Bluetooth Smart ZigBee/Thread ZigBee RC Proprietary 	Full	19.5
EFR32MG1P232F256GM48-B0	2.4 GHz	M4	256	32	 Bluetooth Smart ZigBee/Thread ZigBee RC Proprietary 	Full	19.5
EFR32MG1B232F256GM48-B0	2.4 GHz	M4	256	32	 ZigBee/Thread ZigBee RC	Full	19.5



Figure 2.1. OPN Decoder

3. System Overview

3.1 Introduction

The EFR32 product family features the world's most energy friendly System-on-Chip radios. The devices are well suited for any battery operated application as well as other systems requiring high performance and low energy consumption. This section gives a short introduction to the full radio and MCU system. The detailed functional description can be found in the EFR32 Reference Manual.

3.2 Block Diagram

A block diagram of the EFR32MG1X232 is shown in Figure 3.1 Block Diagram on page 3.





3.3 System Description

3.3.1 Antenna interface

The 2.4 GHz antenna interface consists of two pins (2GRF_IOP and 2GRF_ION) that interface directly to the on-chip BALUN. The 2GRF_ION pin should be grounded externally.

The external components and power supply connections for the antenna interface in a typical application are shown in Section 5. Application Circuits.

3.3.2 Integrated Oscillators

The EFR32MG1X232 supports two crystal oscillators and fully integrates four RC oscillators, listed below.

- A high frequency crystal oscillator (HFXO) with integrated load capacitors, tunable in small steps, provides a precise timing reference for the radio and MCU. Crystal frequencies in the range from 38 to 40 MHz are supported. Silicon Laboratories reference designs employ a crystal frequency of 38.4 MHz. An external clock source such as a TCXO can also be applied to the HFXO input for improved accuracy over temperature.
- An optional 32.768 kHz crystal oscillator (LFXO) can be used as an accurate timing reference in low energy modes.
- · A 32.768 kHz crystal oscillator (LFXO) should be used as an accurate timing reference in Bluetooth Smart low energy modes.
- An integrated high frequency RC oscillator (HFRCO) is available for the MCU system, when crystal accuracy is not required. The HFRCO employs fast startup at minimal energy consumption combined with a wide frequency range.
- An integrated auxilliary high frequency RC oscillator (AUXHFRCO) is available for timing the general-purpose ADC and the Serial Wire debug port with a wide frequency range.
- An integrated low frequency 32.768 kHz RC oscillator (LFRCO) can be used as a timing reference in low energy modes, when crystal accuracy is not required.
- An integrated ultra-low frequency 1 kHz RC oscillator (ULFRCO) is available to provide a timing reference at the lowest energy consumption in low energy modes.

3.3.3 Fractional-N Frequency Synthesizer

The EFR32MG1X232 contains a high performance, low phase noise, fully integrated fractional-N frequency synthesizer. The synthesizer is used in receive mode to generate the LO frequency used by the down-conversion mixer. It is also used in transmit mode to directly generate the modulated RF carrier.

The fractional-N architecture provides excellent phase noise performance combined with frequency resolution better than 100 Hz, with low energy consumption. The synthesizer has fast frequency settling which allows very short receiver and transmitter wake up times to optimize system energy consumption.

3.3.4 Receiver Architecture

The EFR32MG1X232 uses a low-IF receiver architecture, consisting of a Low-Noise Amplifier (LNA) followed by an I/Q down-conversion mixer, emplying a 38.4 MHz crystal reference. The I/Q signals are further filtered and amplified before being sampled by the IF analog-to-digital converter (IFADC).

The IF frequency is configurable from 150 kHz to 1371 kHz. The IF can further be configured for high-side or low-side injection, providing flexibility with respect to known interferers at the image frequency.

The Automatic Gain Control (AGC) module adjusts the receiver gain to optimize performance and avoid saturation for excellent selectivity and blocking performance.

Demodulation is performed in the digital domain. The demodulator performs configurable decimation and channel filtering to allow receive bandwidths ranging from 0.1 to 2530 kHz. High carrier frequency and baud rate offsets are tolerated by active estimation and compensation. Advanced features supporting high quality communication under adverse conditions include forward error correction by block and convolutional coding as well as Direct Sequence Spread Spectrum (DSSS).

A Received Signal Strength Indicator (RSSI) is available for signal quality metrics, for level-based proximity detection, and for RF channel access by Collision Avoidance (CA) or Listen Before Talk (LBT) algorithms. An RSSI capture value with dB resolution is associated with each received frame and the dynamic RSSI measurement can be monitored throughout reception.

The EFR32MG1X232 features integrated support for antenna diversity to improve link budget, using complementary control outputs to an external switch. Internal configurable hardware controls automatic switching between antennae during RF receive detection operations.

In typical applications, the demodulator output is stored in internal buffer memory for access by the MCU. Direct mode supports direct serial output of demodulated data on configured GPIO pins.

3.3.5 Transmitter Architecture

The EFR32MG1X232 uses a direct-conversion transmitter architecture. For constant envelope modulation formats, the modulator controls phase and frequency modulation in the frequency synthesizer. Transmit symbols or chips are optionally shaped by a digital shaping filter. The shaping filter is fully configurable, including the BT product, and can be used to implement Gaussian or Raised Cosine shaping.

Automated PA up and down ramping is applied to each transmitted frame, in order to ensure the Adjacent Channel Power (ACP) meets regulatory requirements.

Carrier Sense Multiple Access - Collision Avoidance (CSMA-CA) or Listen Before Talk (LBT) algorithms can be automatically timed by the EFR32MG1X232. These algorithms are typically defined by regulatory standards to improve inter-operability in a given bandwidth between devices that otherwise lack synchronized RF channel access.

3.3.6 Wake on Radio

The Wake on Radio feature allows flexible, autonomous RF sensing, qualification, and demodulation without required MCU activity, using a subsystem of the EFR32MG1X232 including the Radio Controller (RAC), Peripheral Reflex System (PRS), and Low Energy peripherals. Wake on Radio implementation may typically include the following functionality:

- Periodic trigger to start RF evaluation from the RTCC, GPIO or other low energy peripherals
- Received Signal Strength Indicator (RSSI) qualification
- Preamble and frame sync qualification
- · Frame header qualification, including address filtering
- · Autonomous packet demodulation and buffering
- · Optional transfer of RSSI values to RAM via DMA
- Timeout to disable the receiver through the PRS in case of false alarm

3.3.7 RFSENSE

The RFSENSE module generates a system wakeup interrupt upon detection of wideband RF energy at the antenna interface, providing true RF wakeup capabilities from low energy modes including EM2, EM3 and EM4.

RFSENSE triggers on a relatively strong RF signal and is available in the lowest energy modes, allowing exceptionally low energy consumption. RFSENSE does not demodulate or otherwise qualify the received signal, but software may respond to the wakeup event by enabling normal RF reception.

Various strategies for optimizing power consumption and system response time in presence of false alarms may be employed using available timer peripherals.

3.3.8 Flexible Frame Handling

EFR32MG1X232 has an extensive and flexible frame handling support for easy implementation of even complex communication protocols. The Frame Controller (FRC) supports all low level and timing critical tasks together with the Radio Controller and Modulator/ Demodulator:

- Highly adjustable preamble length
- · Up to 2 simultaneous synchronization words, each up to 32 bits and providing separate interrupts
- Frame disassembly and address matching (filtering) to accept or reject frames
- Automatic ACK frame assembly and transmission
- Fully flexible CRC generation and verification:
 - Multiple CRC values can be embedded in a single frame
 - 8, 16, 24 or 32-bit CRC value
 - Configurable CRC bit and byte ordering
- Selectable bit-ordering (least significant or most significant bit first)
- Optional data whitening
- Optional Forward Error Correction (FEC), including convolutional encoding / decoding and block encoding / decoding
- Half rate convolutional encoder and decoder with constraint lengths from 2 to 7 and optional puncturing
- Fully configurable block codes for sub-GHz protocols, supporting both linear codes and table based lookup (e.g. Wireless M-bus 3out-of-6 coding)
- · Optional symbol interleaving, typically used in combination with FEC
- Symbol coding, such as Manchester or DSSS, supported in the MODEM, or biphase space encoding using FEC hardware
- · UART encoding over air, with start and stop bit insertion / removal
- · Test mode support, such as modulated or unmodulated carrier output
- Received frame timestamping

3.3.9 Packet and State Trace

The EFR32MG1X232 Frame Controller has a packet and state trace unit that provides valuable information during the development phase. It features:

- Non-intrusive trace of transmit data, receive data and state information
- Data observability on a single-pin UART data output, or on a two-pin SPI data output
- Configurable data output bitrate / baudrate
- · Multiplexed transmitted data, received data and state / meta information in a single serial data stream

3.3.10 Data Buffering

The EFR32MG1X232 features an advanced buffer controller (BUFC) capable of handling up to 4 buffers of adjustable size from 64 bytes to 4096 bytes. Each buffer can be used for RX, TX or both. The buffer data is located in RAM, enabling zero-copy operations.

3.3.11 Radio Controller (RAC)

The Radio Controller controls the top level state of the radio subsystem in the EFR32MG1X232. It performs the following tasks:

- Precisely-timed control of enabling and disabling of the receiver and transmitter circuitry
- Run-time calibration of receiver, transmitter and frequency synthesizer
- Detailed frame transmission timing, including optional LBT or CSMA-CA

3.3.12 Crypto Accelerator (CRYPTO)

The Crypto Accelerator is a fast and energy-efficient autonomous hardware encryption and decryption accelerator. EFR32 devices support various levels of hardware-accelerated encryption, depending on the part. Section 2. Ordering Information specifies whether this part has **full** or **AES-only** crypto support. AES-only devices support AES encryption and decryption with 128- or 256-bit keys. Full crypto support adds RSA-2048, ECC over both GF(P) and GF(2^m), SHA-1 and SHA-2.

Supported modes of operation for AES includes ECB, CTR, CBC, PCBC, CFB, OFB, CBC-MAC, GMAC, CCM and GCM.

Supported ECC NIST recommended curves include P-192, P-224, P-256, K-163, K-233, B-163 and B-233.

The CRYPTO is tightly linked to the BUFC enabling fast and efficient autonomous cipher operations on data buffer content. It allows fast processing of ECC, RSA and SHA with little CPU intervention. CRYPTO also provides trigger signals for DMA read and write operations.

3.3.13 True Random Number Generator

The Frame Controller (FRC) implements a true random number generator that extracts noise from the RF receive chain. Data can be read from a register 32 bits at a time, or larger blocks of random data can be written directly to RAM.

Output from the random number generator can be used either directly or as a seed or entropy source for software based random number generator algorithms such as Fortuna.

3.3.14 System Processor

The ARM Cortex-M processor subsystem integrates the following features and tasks in the system:

- 32-bit ARM Cortex-M RISC processor achieving 1.25 Dhrystone MIPS/MHz
- Memory Protection Unit (MPU) supporting up to 8 memory segments
- Up to 256 kB flash program memory
- Up to 32 kB RAM data memory
- Advanced and flexible protocol support, in cooperation with the Frame Controller
- · Configuration and event handling of all modules
- · 2-pin Serial-Wire debug interface, which can be disabled

The Cortex-M4 is equipped with DSP instruction support and a floating-point unit (FPU).

3.3.15 Memory System Controller (MSC)

The Memory System Controller (MSC) is the program memory unit of the microcontroller. The flash memory is readable and writable from both the Cortex-M and DMA. The flash memory is divided into two blocks; the main block and the information block. Program code is normally written to the main block, whereas the information block is available for special user data and flash lock bits. There is also a read-only page in the information block containing system and device calibration data. Read and write operations are supported in energy modes EM0 Active/EM1 Sleep.

3.3.16 Linked Direct Memory Access Controller (LDMA)

The Linked Direct Memory Access (LDMA) controller features 8 channels capable of performing memory operations independently of software. This reduces both energy consumption and software workload.

3.3.17 Integrated Voltage Regulators

The EFR32MG1X232 generates internal supply voltages from integrated regulators. This means that only a single external supply voltage is required, from which all internal voltages are created. An optional integrated DC-DC buck regulator, further detailed in section 3.3.37 Integrated DC-DC Converter (DC-DC), can be utilized to further reduce the current consumption. The DC-DC regulator requires one external inductor and one external capacitor.

3.3.18 Reset Management Unit (RMU)

The RMU is responsible for handling reset of the EFR32MG1X232. A wide range of reset sources are available, including several power supply monitors, pin reset, software controlled reset, core lockup reset and watchdog reset.

3.3.19 Energy Management Unit (EMU)

The Energy Management Unit manages transitions of energy modes in the device. Each energy mode defines which peripherals and features are available. The EMU can also be used to turn off the power to unused RAM blocks. The EMU also contains control registers for the DC-DC regulator and the Voltage Monitor (VMON). The VMON is used to monitor multiple supply voltages. It has 4 channels which can be programmed individually by the user to determine if a sensed supply has fallen below a chosen threshold.

3.3.20 Clock Management Unit (CMU)

The Clock Management Unit controls oscillators and clocks in the EFR32MG1X232. Individual enabling and disabling of clocks to all peripheral modules is performed by the CMU. The CMU also controls enabling and configuration of the oscillators. A high degree of flexibility allows software to optimize energy consumption in any specific application by minimizing power dissipation in unused peripherals and oscillators.

3.3.21 Watchdog (WDOG)

The watchdog timer with window monitoring capabilities can monitor the Peripheral Reflex System and generate a reset in case of a system failure to improve application reliability.

3.3.22 Peripheral Reflex System (PRS)

The Peripheral Reflex System provides a communication network between different peripheral modules without software involvement. Peripheral modules producing Reflex signals are called producers. The PRS routes Reflex signals from producers to consumer peripherals which in turn perform actions in response. Edge triggers and other functionality can be applied by the PRS. The PRS allows peripheral to act autonomously without waking the MCU core, saving power.

3.3.23 Universal Synchronous/Asynchronous Receiver/Transmitter (USART)

The Universal Synchronous/Asynchronous Receiver/Transmitter is a flexible serial I/O module. It supports full duplex asynchronous UART communication with hardware flow control as well as RS-485, SPI, MicroWire and 3-wire. It can also interface with devices supporting:

- ISO7816 SmartCards
- IrDA
- 1²S

3.3.24 Low Energy Universal Asynchronous Receiver/Transmitter (LEUART)

The unique LEUART provides two-way UART communication on a strict power budget. Only a 32.768 kHz clock is needed to allow UART communication up to 9600 baud. The LEUART includes all necessary hardware to make asynchronous serial communication possible with a minimum of software intervention and energy consumption.

3.3.25 Inter-Integrated Circuit Interface (I²C)

The I²C module provides an interface between the MCU and a serial I²C bus. It is capable of acting as both a master and a slave and supports multi-master buses. Standard-mode, fast-mode and fast-mode plus speeds are supported, allowing transmission rates from 10 kbit/s up to 1 Mbit/s. Slave arbitration and timeouts are also available, allowing implementation of an SMBus-compliant system. The interface provided to software by the I²C module allows precise timing control of the transmission process and highly automated transfers. Automatic recognition of slave addresses is provided in active and low energy modes.

3.3.26 Protocol Timer (PROTIMER)

The PROTIMER is perfectly suited for radio protocol time-keeping, featuring support for time-slotted and random backoff LBT/CSMA radio access mechanisms. The PROTIMER includes a capture/compare functionality, including several capture registers, configurable to capture counter or RTCC values upon trigger events selected from Peripheral Reflex System events or radio events. The capture register values may be used for received frame timestamping. The compare feature produces output events upon match of captured values to programmed comparison values, which can be used to enable or disable the RF receiver without MCU intervention.

3.3.27 Timer/Counter (TIMER)

TIMER peripherals keep track of timing, count events, generate PWM outputs and trigger timed actions in other peripherals through the PRS system. Please refer to Section 3.4 Configuration Summary for available TIMER units and features in the EFR32MG1X232

The core of each TIMER is a 16-bit counter with up to 4 compare/capture channels. Each channel is configurable in one of three modes. In capture mode, the counter state is stored in a buffer at a selected input event. In compare mode, the channel output reflects the comparison of the counter to a programmed threshold value. In PWM mode, the TIMER supports generation of pulse-width modulation (PWM) outputs of arbitrary waveforms defined by the sequence of values written to the compare registers, with optional dead-time insertion available in timer unit TIMER_0 only.

3.3.28 Real Time Counter and Calendar (RTCC)

The Real Time Counter and Calendar (RTCC) is a 32-bit counter providing timekeeping in all energy modes. The RTCC includes a Binary Coded Decimal (BCD) calendar mode for easy time and date keeping. The RTCC can be clocked by any of the on-board oscillators (Section 3.3.2 Integrated Oscillators) with the exception of the AUXHFRCO, and it is capable of providing system wake-up at user defined instances. When receiving frames, the RTCC value can be used for timestamping. The RTCC includes 128 bytes of general purpose data retention, allowing easy and convenient data storage in all energy modes.

3.3.29 Low Energy Timer (LETIMER[™])

The unique LETIMER, is a 16-bit timer that is available in energy mode EM2 DeepSleep in addition to EM1 Sleep and EM0 Active. This allows it to be used for timing and output generation when most of the device is powered down, allowing simple tasks to be performed while the power consumption of the system is kept at an absolute minimum. The LETIMER can be used to output a variety of waveforms with minimal software intervention. It is also connected to the Real Time Counter and Calendar (RTCC), and can be configured to start counting on compare matches from the RTCC.

3.3.30 Ultra Low Power Wake-up Timer (CRYOTIMER)

The CRYOTIMER is a 32-bit counter that is capable of running in all energy modes. It can be clocked by either the 32.768 kHz crystal oscillator (LFXO), the 32.768 kHz RC oscillator (LFRCO) or the 1 kHz RC oscillator (ULFRCO). It can provide periodic Wakeup events and PRS signals which can be used to wake up peripherals from any energy mode. The CRYOTIMER provides a wide range of interrupt periods, facilitating flexible ultra-low energy operation.

3.3.31 Pulse Counter (PCNT)

The Pulse Counter (PCNT) peripheral can be used for counting pulses on a single input or to decode quadrature encoded inputs. The clock for PCNT is selectable from either an external source on pin PCTNn_S0IN or from an internal timing reference, selectable from among any of the internal oscillators, except the AUXHFRCO. The module may operate in energy mode EM0 Active, EM1 Sleep, EM2 DeepSleep and EM3 Stop.

3.3.32 General Purpose Input/Output (GPIO)

EFR32MG1X232 has 31 General Purpose Input/Output pins. Each GPIO pin can be individually configured as either an output or input. More advanced configurations including open-drain, open-source, and glitch-filtering can be configured for each individual GPIO pin. The GPIO pins can be overridden by peripheral connections, like SPI communication. Each peripheral connection can be routed to several GPIO pins on the device. The input value of a GPIO pin can be routed through the Peripheral Reflex System to other peripherals. The GPIO subsystem supports asynchronous external pin interrupts.

3.3.33 Analog Port (APORT)

The Analog Port (APORT) is an analog interconnect matrix allowing access to analog modules ADC, ACMP, and IDAC on a flexible selection of pins. Each APORT bus consists of analog switches connected to a common wire. Since many clients can operate differentially, buses are grouped by X/Y pairs. See 6.4 Analog Port (APORT) for an illustration of the APORT connections.

3.3.34 Analog Comparator (ACMP)

The Analog Comparator is used to compare the voltage of two analog inputs, with a digital output indicating which input voltage is higher. Inputs are selected from among internal references and external pins. The tradeoff between response time and current consumption is configurable by software.

The ACMP can also be used to monitor the supply voltage from software. An interrupt can be generated when the supply falls below or rises above a programmable threshold.

3.3.35 Analog to Digital Converter (ADC)

The ADC is a Successive Approximation Register (SAR) architecture, with a resolution of up to 12 bits at up to 1 MSamples/s. The output sample resolution is configurable and additional resolution is possible using integrated hardware for averaging over multiple samples.

The ADC includes integrated voltage references and an integrated temperature sensor. Inputs are selectable from a wide range of source, including pins configurable as either single-ended or differential.

3.3.36 Digital to Analog Current Converter (IDAC)

The Digital to Analog Current Converter can source or sink a configurable constant current. This current can be driven on an output pin or routed to the selected ADC input pin for capacitive sensing. The current is programmable between 0.05 μ A and 64 μ A with several ranges with various step sizes.

3.3.37 Integrated DC-DC Converter (DC-DC)

The DC-DC buck converter covers a wide range of load currents and provides high efficiency in energy modes EM0, EM1, EM2 and EM3. Patent-pending RF noise mitigation allows operation of the DC-DC converter without degrading radio sensitivity. The converter has three modes: low noise (LN), low power (LP), and bypass. Each operating mode transition is initiated by firmware and executed by an integrated hardware state machine, providing well-controlled transitions. Bypass mode may be entered when the input voltage is too low for efficient operation of the DC-DC converter. In Bypass mode, the DC-DC input supply is internally connected directly to its output through a low resistance switch. Bypass mode also supports in-rush current limiting to avoid dipping the input supply due to excessive current transients.

Key Features:

- Wide load range from sub-µA to 200 mA
- High efficiency up to 90%
- · Low Noise (LN), Low Power (LP) and Bypass operating modes for high performance and low energy applications
 - · Fast wakeup from LP to LN to support quick EM2 to EM0 transition
 - · Low 50 nA quiescent current in LP mode to support micro-ampere range load currents
- · Optimized for integration with the on-board radio
 - · Switching frequency programmable from 3 MHz to 8 MHz
 - · RF noise mitigation mechanism
- · Supports wide range of passive part selection
- External capacitor range from 1 μF to 10 μF with external 4.7 μH inductor
- Protection features
 - Programmable sourcing and sinking current limits
 - Output short-circuit protection
 - Dead-time protection





3.3.37.1 DC-DC Converter Powertrain

The powertrain consists of low-resistance P-channel (PFET1) and N-channel (NFET) switches, combined with a current limiter and zero-crossing detector. The power switches provide programmable drive strength by selection of a number of slices for each switch. The switching logic takes either a PWM signal from a low-noise controller or pulses from a low-power controller and drives PFET1 and NFET switches using proper dead-time control. The powertrain can switch in both forced Continuous Conduction Mode (CCM) mode and load-adaptive Continuous Conduction/Discontinuous Conduction (CCM/DCM) mode. Load-adaptive CCM/DCM mode has superior efficiency in light load conditions, whereas forced CCM mode provides the best transient response and noise control when the radio is on.

The DC-DC converter includes a current limiter to protect PFET1 from large transient currents. Whenever a current overload is detected, the switching logic advances the transition from PFET1 to NFET and optionally sends an interrupt signal to the processor.

A zero-voltage detector is included to prevent reverse current in DCM mode. When NFET is on and zero voltage is detected across NFET, the switching logic will turn NFET off to prevent reverse current. The zero-voltage detector can be disabled to enable forced CCM mode. It can also be configured as a programmable reverse current limiter.

3.3.37.2 DC-DC Converter Low Noise (LN) Controller

The LN controller consists of an active-RC type-III compensator, a ramp generator and a PWM comparator. The compensator generates an error voltage from on-chip feedback, which is compared against a ramp voltage by the PWM comparator. The resulting PWM signal is duty-cycle limited between 3% and 96%, with circuitry to avoid control-loop lockout. The PWM frequency can be generated from the ramp generator's oscillator or from an external clock from the radio's RF synthesizer. Noise mitigation hardware post-processes the PWM signal to avoid in-band noise coupling into the radio system.

3.3.37.3 DC-DC Converter Low Power (LP) Controller

The LP controller consists of a continuous-time comparator with hysteresis and a constant frequency pulse generator. When the output voltage is lower than the low threshold of the comparator, the pulse generator is enabled to activate the powertrain. The powertrain switches at a constant-frequency with a fixed duty cycle of about 90%. When the DC-DC output exceeds the comparator's high threshold, the pulse generator is disabled until the cycle starts over again on the next low-threshold crossing. The comparator has four programmable response-time settings. The lowest setting consumes only approximately 50nA, providing high-efficiency regulation of current loads down to the micro-ampere range.

3.4 Configuration Summary

The features of the EFR32MG1X232 is a subset of the feature set described in the EFR32 Reference Manual. Table 3.1 Configuration Summary on page 11 describes device specific implementation of the features. Remaining modules support full configuration.

Table 3.1. Configuration Summary

Module	Configuration	Pin Connections
USART0	IrDA I ² S SmartCard	US0_TX, US0_RX, US0_CLK, US0_CS
USART1	IrDA I ² S SmartCard	US1_TX, US1_RX, US1_CLK, US1_CS
TIMER0	with DTI.	TIM0_CC[2:0], TIM0_CDTI[2:0]
TIMER1		TIM1_CC[3:0]

3.5 Memory Map

The EFR32MG1X232 memory map is shown in the figure below. RAM and flash sizes are for the largest memory configuration.



Figure 3.3. EFR32MG1X232 Memory Map

4. Electrical Characteristics

4.1 Test Conditions

4.1.1 Typical Values

Typical values are based on T_{AMB} =25 °C and V_{DD} =3.3 V, as defined in 4.3.1 General Operating Conditions, by production test and/or technology characterization unless otherwise specified.

Radio performance numbers are measured in conducted mode, based on Silicon Labs reference designs using output power-specific external RF impedance-matching networks, further identified in Section 5. Application Circuits, for interfacing to a 50 Ω antenna.

4.1.2 Minimum and Maximum Values

Minimum and maximum values represent the worst conditions of ambient temperature, supply voltage and frequencies, as defined in 4.3.1 General Operating Conditions.

4.2 Absolute Maximum Ratings

The absolute maximum ratings are stress ratings, and functional operation under such conditions is not guaranteed. Stress beyond the limits specified in may affect the device reliability or cause permanent damage to the device. Functional operating conditions are given in 4.3.1 General Operating Conditions.

Parameter	Symbol	Test Condition	Mi	n Typ	Мах	Unit
Storage temperature range	T _{STG}		-50) -	150	°C
External main supply voltage	V _{DDMAX}		0	-	3.8	V
External main supply voltage ramp rate	V _{DDRAMPMAX}		-	-	1	V / µs
Voltage on any 5V tolerant GPIO pin ¹	V _{DIGPIN}		-0.	3 -	Min of 5.25 and IOVDD +2	V
Voltage on non-5V tolerant GPIO pins			-0.	3 -	IOVDD+0.3	V
Voltage on HFXO pins	V _{HFXOPIN}	_	-0.	3 -	1.4	V
Voltage on RF pins 2G4RF_IOP and 2G4RF_ION	V _{MAX2G4}	_	ТВ	D -	TBD	V
Total current into V _{SS} ground lines (sink)	IVSSMAX	_	-	-	TBD	mA
Current per I/O pin (sink)	I _{IOMAX}		-	-	50	mA
Current per I/O pin (source)			-	-	50	mA
Current for all I/O pins (sink)	I _{IOALLMAX}		-	-	TBD	mA
Current for all I/O pins (source)	-		-	-	TBD	mA
Voltage difference between AVDD and VREGVDD	ΔV _{DD}		-	-	0.3	V
	1	1	1	1		

Table 4.1. Absolute Maximum Ratings

Note:

1. When a GPIO pin is routed to the analog module through the APORT, the maximum voltage = IOVDD.

4.3 Operating Conditions

When assigning supply sources, the following requirements must be observed:

- VREGVDD must be the highet voltage in the system
- VREGVDD ≥ AVDD
- VREGVDD ≥ DVDD
- DVDD ≥ PAVDD
- DVDD ≥ DECOUPLE
- AVDD ≥ IOVDD

4.3.1 General Operating Conditions

Table 4.2. General Operating Conditions

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Ambient temperature range	T _{AMB}		-40	25	85	°C
VREGVDD Operating supply voltage	V _{VREGVDD}		1.62	3.3	3.8	V
RFVDD Operating supply voltage	V _{RFVDD}		1.62	-	V(VREGVD D)	V
AVDD Operating supply volt- age	V _{AVDD}	AVDD must be tied to VREGVDD	V(VREGVD D)	-	V(VREGVD D)	V
DVDD Operating supply volt- age	V _{DVDD}		1.62	-	V(VREGVD D)	V
PAVDD Operating supply voltage	V _{PAVDD}		1.62	-	3.8	V
IOVDD Operating supply voltage	V _{IOVDD}		1.62	-	V(VREGVD D)	V
DECOUPLE Operating sup- ply voltage	V _{DECOUPLE}		1.08	1.2	1.32	V
Difference between AVDD and VREGVDD, ABS(AVDD- VREGVDD)	dV _{DD}				0.1	V
HFCLK frequency	f _{CORE}	0 wait-states (MODE = WS0) ¹	-	-	26	MHz
		1 wait-states (MODE = WS1) ¹	-	38.4	40	MHz

1. in MSC_READCTRL register

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4.4 DC-DC Converter

Test conditions: L_{DCDC} =4.7 µH, C_{DCDC} =1.0 µF, $V_{DCDC_{I}}$ =3.3 V, $V_{DCDC_{O}}$ =1.8 V, $I_{DCDC_{LOAD}}$ =50 mA, Heavy Drive configuration, $F_{DCDC_{LN}}$ =8 MHz, unless otherwise indicated.

Table 4.3. DC-DC Converter

Parameter	Symbol	Test Condition	Min	Тур	Мах	Unit
Input voltage range	V _{DCDC_I}	Bypass mode	TBD	-	3.8	V
		Low noise (LN) or low power (LP) mode, 1.8 V output, 200 mA load current	2.4	-	3.8	V
Output voltage range	V _{DCDC_} O	1.8V configuration	1.8	-	-	V
Steady-state output ripple	V _R	ESR=50 Ω , ESL=2 nH on 1 μ F filter cap. Radio disabled	-	3	-	mVpp
		ESR=50 Ω , ESL=2 nH on 1 μ F filter cap. Radio enabled	-	TBD	-	mVpp
Output voltage under/over- shoot	V _{OV}	CCM Mode (LNFORCECCM ¹ = 1), Load changes between 0 mA and 100 mA	-	100	-	mV
		DCM Mode (LNFORCECCM ¹ = 0), Load changes between 0 mA and 10 mA	-	150	-	mV
DC line regulation	V _{REG}	Input changes between 3.8 V and 2.4 V	-	0.1	-	%
DC load regulation	I _{REG}	Load changes between 0 mA and 100 mA in CCM mode	-	0.1	-	%
Quiescent current	IDCDC_Q	Low power (LP) mode, lowest bias setting (LPCMPBIAS ¹ = BIAS0)		50	-	nA
		Low noise (LN) mode, DCM con- figuration (LNFORCECCM ¹ = 0)	-	0.3	-	mA
		Low noise (LN) mode, CCM con- figuration (LNFORCECCM ¹ = 1)	-	0.8	-	mA
Max load current	I _{LOAD_MAX}	Low noise (LN) mode	-		200	mA
		Low power (LP) mode	-		- - - - - - - - - - - - - - - - - - -	mA
Capacitance of DCDC output capacitor	C _{DCDC}		1	-	10	μF
Inductance of DCDC output inductor	L _{DCDC}		-	4.7	-	μH
Resistance in Bypass mode	R _{BYP}		-	0.8	-	Ω
Peak current limit range	I _{IPK}		20	-	640	mA
Peak current limit step	I _{PK_STEP}	Light drive ²	-	20	-	mA
		Medium Drive ²	-	40	-	mA
		Heavy Drive ²	-	80	-	mA
Switching frequency	F _{LN}	Low noise (LN) mode	3		8	MHz

Parameter	Symbol	Test Condition	Min	Тур	Мах	Unit
Note:						
1. In MU_DCDCMISCCT	RL register					
2. Drive levels are defined	by configuration	of the P/NSLICESEL register. Light	Drive: P/NSLICE	SEL=3; Medi	um Drive: P/N	ISLICE-

SEL=7; Heavy Drive: P/NSLICESEL=15.

4.4.1 DC-DC Converter Typical Performance Characteristics

 $Default \ test \ conditions: \ CCM \ mode, \ L_{DCDC}=4.7 \ \mu H, \ C_{DCDC}=1.0 \ \mu F, \ V_{DCDC_I}=3.3 \ V, \ V_{DCDC_O}=1.8 \ V, \ F_{DCDC_LN}=8 \ MHz$





4.5 Current Consumption

4.5.1 Current Consumption 1.8 V without DC-DC Converter

Unless otherwise indicated VREGVDD = AVDD = DVDD = RFVDD = PAVDD= 1.8 V. EMU_PWRCFG_PWRCG=NODCDC. EMU_DCDCCTRL_DCDCMODE=BYPASS. See Figure 5.1 EFR32MG1X232 Typical Application Circuit: Direct Supply Configuration without DC-DC converter on page 44.

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Current consumption in EM0 Active mode with radio disa-	I _{ACTIVE}	38.4 MHz crystal, CPU running while loop from flash	-	TBD	-	µA/MHz
bled, All peripherals disabled		38 MHz HFRCO, CPU running Prime from flash	-	TBD	-	µA/MHz
		38 MHz HFRCO, CPU running while loop from flash	-	TBD	-	µA/MHz
		38 MHz HFRCO, CPU running CoreMark from flash	-	TBD	-	µA/MHz
		26 MHz HFRCO, CPU running while loop from flash	-	TBD	-	µA/MHz
		1 MHz HFRCO, CPU running while loop from flash	-	TBD	-	µA/MHz
Current consumption in EM1	I _{IDLE}	38.4 MHz crystal	-	TBD	-	µA/MHz
Sleep mode with radio disabled. All peripherals disabled		38 MHz HFRCO	-	TBD	-	µA/MHz
		26 MHz HFRCO	-	TBD	-	µA/MHz
		1 MHz HFRCO	-	TBD	_	µA/MHz
Current consumption in EM2 DeepSleep mode.	I _{EM2}	Full RAM retention and RTCC running from LFXO	-	TBD	-	μA
Current consumption in EM3 Stop mode	I _{EM3}	Full RAM retention and CRYO- TIMER running from ULFRCO		TBD	-	μA
Current consumption in EM4 Hibernate mode	I _{EM4}	128 byte RAM retention, RTCC running from LFXO		TBD	-	μA
		128 byte RAM retention, CRYO- TIMER running from ULFRCO	-	TBD	5	μA
		128 byte RAM retention, no RTCC	-	TBD	-	μA
Current consumption in EM4 Shutoff mode	I _{EM4S}	No RAM retention, no RTCC	-	TBD	-	μA

Table 4.4. Current Consumption 1.8V without DC/DC

4.5.2 Current Consumption 3.3 V without DC-DC Converter

Unless otherwise indicated VREGVDD = AVDD = DVDD = RFVDD = PAVDD= 3.3 V. EMU_PWRCFG_PWRCG=NODCDC. EMU_DCDCCTRL_DCDCMODE=BYPASS. See Figure 5.1 EFR32MG1X232 Typical Application Circuit: Direct Supply Configuration without DC-DC converter on page 44.

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Current consumption in EM0 Active mode with radio disa-	IACTIVE	38.4 MHz crystal, CPU running while loop from flash	-	124	-	µA/MHz
bled, All peripherals disabled		38 MHz HFRCO, CPU running Prime from flash	-	85	-	µA/MHz
		38 MHz HFRCO, CPU running while loop from flash	-	99	-	µA/MHz
		38 MHz HFRCO, CPU running CoreMark from flash	-	TBD	-	µA/MHz
		26 MHz HFRCO, CPU running while loop from flash	-	100	-	µA/MHz
		1 MHz HFRCO, CPU running while loop from flash	-	TBD	-	µA/MHz
Current consumption in EM1	I _{IDLE}	38.4 MHz crystal	-	45	-	µA/MHz
Sleep mode with radio disabled. All peripherals disabled		38 MHz HFRCO	-	27	-	µA/MHz
		26 MHz HFRCO	-	28	-	µA/MHz
		1 MHz HFRCO	-	TBD	-	µA/MHz
Current consumption in EM2 DeepSleep mode.	I _{EM2}	Full RAM retention and RTCC running from LFXO	-	2.92	-	μΑ
Current consumption in EM3 Stop mode	I _{EM3}	Full RAM retention and CRYO- TIMER running from ULFRCO		TBD	-	μΑ
Current consumption in EM4 Hibernate mode	I _{EM4}	128 byte RAM retention, RTCC running from LFXO		TBD	-	μΑ
		128 byte RAM retention, CRYO- TIMER running from ULFRCO	-	TBD	-	μΑ
		128 byte RAM retention, no RTCC	-	TBD	o -	μA
Current consumption in EM4 Shutoff mode	I _{EM4S}	no RAM retention, no RTCC	-	TBD	-	μΑ

Table 4.5. Current Consumption 3.3V without DC/DC

4.5.3 Current Consumption 3.3 V using DC-DC Converter

Unless otherwise indicated VREGVDD = AVDD = IOVDD = 3.3 V, DVDD = RFVDD = PAVDD= 1.8 V DC-DC output. See Figure 5.2 EFR32MG1X232 Typical Application Circuit: Configuration with DC-DC Coverter (PAVDD from VDCDC) on page 44 or Figure 5.3 EFR32MG1X232 Typical Application Circuit: Configuration with DC-DC Coverter (PAVDD from VDD) on page 45.

Parameter	Symbol	Test Condition	Min	Тур	Мах	Unit
Current consumption in EM0 Active mode with radio disa-	IACTIVE	38.4 MHz crystal, CPU running while loop from flash.	-	94	-	µA/MHz
bled. All peripherals disa- bled, DCDC in LowNoise mode		38 MHz HFRCO, CPU running Prime from flash	-	60	-	µA/MHz
		38 MHz HFRCO, CPU running while loop from flash	-	69	-	µA/MHz
		38 MHz HFRCO, CPU running CoreMark from flash	-	TBD	-	µA/MHz
		26 MHz HFRCO, CPU running while loop from flash	-	75	-	µA/MHz
		1 MHz HFRCO, CPU running while loop from flash	-	TBD	-	µA/MHz
Current consumption in EM1	I _{IDLE}	38.4 MHz crystal	-	39	-	µA/MHz
Sleep mode with radio disabled. All peripherals disa-		38 MHz HFRCO	-	20	-	µA/MHz
bled, DCDC in LowPower mode.		26 MHz HFRCO	-	21	-	µA/MHz
		1 MHz HFRCO	-	TBD	-	µA/MHz
Current consumption in EM2 DeepSleep mode.	I _{EM2}	Full RAM retention and RTCC running from LFXO ¹	-	1.35	-	μΑ
Current consumption in EM3 Stop mode	I _{EM3}	Full RAM retention and CRYO- TIMER running from ULFRCO ²		1	-	μΑ
Current consumption in EM4 Hibernate mode	I _{EM4}	128 byte RAM retention, RTCC running from LFXO	-	0.7	-	μΑ
		128 byte RAM retention, CRYO- TIMER running from ULFRCO	-	0.5	-	μA
		128 byte RAM retention, no RTCC	-	0.3		μA
Current consumption in EM4 Shutoff mode	I _{EM4S}	no RAM retention, no RTCC	-	0.2	-	μA

Table 4.6. Current Consumption 3.3V with DC/DC

Note:

1. Target for planned revision. Current silicon performance is 2.3 µA

2. Target for planned revision.

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4.5.4 Current Consumption Using Radio

Unless otherwise indicated VREGVDD = AVDD = IOVDD = 3.3 V, DVDD = RFVDD = PAVDD. See Figure 5.2 EFR32MG1X232 Typical Application Circuit: Configuration with DC-DC Coverter (PAVDD from VDCDC) on page 44. or Figure 5.3 EFR32MG1X232 Typical Application Circuit: Configuration with DC-DC Coverter (PAVDD from VDD) on page 45.

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Current consumption in re-	I _{RX}	1 Mbit/s, 2GFSK, F = 2.4 GHz	-	8.6	-	mA
ceive mode, active packet reception (MCU in EM1 @ 38.4 MHz, peripheral clocks disabled)		802.15.4 receiving frame, F = 2.4 GHz	-	9.1	-	mA
Current consumption in pol- led RX mode (radio active for 200 µs every second to check for traffic)	IRX_POLL	1 Mbit/s, 2GFSK, F = 2.4 GHz	-	4	-	μA
Current consumption in	I _{TX}	CW, 0 dBm, F = 2.4 GHz	-	8.2	-	mA
transmit mode (MCU in EM1 @ 38.4 MHz, peripheral		CW, 3 dBm, F = 2.4 GHz	-	16.4	-	mA
clocks disabled)		CW, 8 dBm, F = 2.4 GHz	-	25.5	-	mA
		CW, 10.5 dBm, F = 2.4 GHz	-	34.5	-	mA
		CW, 16.5 dBm, F = 2.4 GHz, PAVDD connected directly to ex- ternal 3.3V supply	-	88	-	mA
		CW, 19.5 dBm, F = 2.4 GHz, PAVDD connected directly to ex- ternal 3.3V supply	-	133	-	mA

Table 4.7. Current Consumption Using Radio 3.3 V with DC-DC

4.6 Wake up times

Parameter	Symbol	Test Condition	Min	Тур	Мах	Unit
Wake up from EM2 Deep-	t _{EM2_WU}	Code execution from RAM	-	2.8	3.4	μs
Sleep		Code execution from FLASH	-	7.8	10.4	μs
Wakeup time from idle, exe- cuting from flash	t IDLE	Executing from flash	-		AHB Clocks	
		Executing from RAM	-	TBD	-	AHB Clocks
Wake up from EM3 Stop	t _{EM3_WU}	Executing from flash	-	2.8	3.4	μs
		Executing from RAM	-	TBD	3.4 10.4 - -	μs
Wake up from EM4 Hiber-	t _{EM4H_WU}	Executing from flash	-	TBD	-	μs
nate ¹		Executing from RAM	-	TBD	-	μs
Wake up from EM4 Shutoff ¹	t _{EM4S_WU}	Executing from flash	-	TBD	-	μs
		Executing from RAM	-	TBD	-	μs

Table 4.8. Wake up times

1. Time from wakeup request till first instruction is executed. Wakeup results in device reset.

4.7 Brown Out Detector

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
DECOUPLE BOD threshold	VDECOUPLEBOD		TBD	TBD	TBD	V
DECOUPLE BOD hysteresis	VDECOU- PLE_HYST	-	-	TBD	-	V
DECOUPLE response time	^t DECOUPLE_DE- LAY	Supply drops at 1V/µs rate	-	TBD	-	nS
DVDDBOD threshold	V _{DVDDBOD}	DVDD rising	TBD	TBD	TBD	V
		DVDD falling	TBD	TBD	TBD	V
DVDD BOD hysteresis	V _{DVDDBOD_HYST}		-	TBD	-	mV
DVDD response time	tDVDDBOD_DELAY	Supply drops at 1V/µs rate	-	TBD	-	nS
AVDD BOD threshold	VAVDDBOD	AVDD rising	TBD	TBD	TBD	V
		AVDD falling	TBD	TBD	- TBD TBD - TBD -	V
AVDD BOD hysteresis	VAVDDBOD_HYST		-	TBD	-	mV
AVDD response time	tavddbod_delay	Supply drops at 1V/µs rate	-	TBD	-	nS
EM4 BOD threshold	V _{EM4DBOD}	AVDD rising	TBD	TBD	TBD	V
		AVDD falling	TBD	TBD	TBD	V
EM4 BOD hysteresis	V _{EM4BOD_HYST}		-	TBD	-	mV
EM4 response time	t _{EM4BOD_DELAY}	Supply drops at 1V/µs rate	-	TBD	-	nS

Table 4.9. Brown Out Detector

4.8 Frequency Synthesizer Characteristics

Table 4.10. Frequency Synthesizer Characteristics

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
RF Synthesizer Frequency range	F _{RANGE_2400}	2.4 GHz frequency range	2400	-	2485	MHz
LO tuning frequency resolu- tion with 38.4 MHz crystal	F _{RES_2400}	2400 - 2485 MHz	-	-	73	Hz
Maximum frequency devia- tion with 38.4 MHz crystal	ΔF _{MAX_2400}		-	-	1677	kHz

4.9 2.4 GHz RF Transceiver Characteristics

4.9.1 RF Transmitter General Characteristics for the 2.4 GHz Band

Unless otherwise indicated T=25C, VREGVDD = AVDD = IOVDD = 3.3 V, DVDD = RFVDD = PAVDD. RFVDD and PAVDD path is filtered using ferrites. Crystal frequency=38.4MHz. RF center frequency 2.440 GHz. Test circuit according to Figure 5.2 EFR32MG1X232 Typical Application Circuit: Configuration with DC-DC Coverter (PAVDD from VDCDC) on page 44 and Figure 5.4 Typical 2.4 GHz RF impedance-matching network circuits on page 45.

Table 4.11.	RF Transmitter Genera	I Characteristics for 2.4 GHz Band
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Symbol	Test Condition	Min	Тур	Мах	Unit
POUT _{MAX}	0 dBm-rated part numbers	-	0	-	dBm
POUT _{MIN}			-62	-	dBm
POUT _{STEP}	-5 dBm< Output power < 0 dBm	-	1	-	dB
POUT _{VAR_V}	1.8 V < V(VREGVDD) < 3.3 V without DC-DC converter	-	6	-	dB
	1.8 V < V(VREGVDD < 3.3 V us- ing DC-DC converter	-	2	-	dB
POUT _{VAR_T}	From -40 to +85° C	-	2	-	dB
POUT _{VAR_F}	Over RF tuning frequency range	-	1	-	dB
F _{RANGE}		2400	-	2483.5	MHz
	POUT _{MAX} POUT _{MIN} POUT _{STEP} POUT _{VAR_V}	POUT_MAX0 dBm-rated part numbersPOUT_MIN-5 dBm< Output power < 0 dBm	POUT_MAX0 dBm-rated part numbers-POUT_MIN-POUT_STEP-5 dBm< Output power < 0 dBm	POUT_MAX0 dBm-rated part numbers-0POUT_MIN-62POUT_STEP-5 dBm< Output power < 0 dBm	POUT_MAX0 dBm-rated part numbers-0-POUT_MIN-62-POUT_STEP-5 dBm< Output power < 0 dBm

1. Supported transmit power levels are determined by the ordering part number (OPN). Transmit power ratings for all devices covered in this datasheet can be found in the Max TX Power column of ^{2. Ordering Information}

4.9.2 RF Receiver General Characteristics for the 2.4 GHz Band

Unless otherwise indicated T=25C, VREGVDD = AVDD = IOVDD = 3.3 V, DVDD = RFVDD = PAVDD. RFVDD and PAVDD path is filtered using ferrites. Crystal frequency=38.4MHz. RF center frequency 2.440 GHz. Test circuit according to Figure 5.2 EFR32MG1X232 Typical Application Circuit: Configuration with DC-DC Coverter (PAVDD from VDCDC) on page 44 and Figure 5.4 Typical 2.4 GHz RF impedance-matching network circuits on page 45.

Table 4.12. RF Receiver General Characteristics for 2.4 GHz Band

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
RF tuning frequency range	F _{RANGE}		2400	-	2483.5	MHz
Receive mode maximum spurious emission	SPUR _{RX}	30 MHz to 1 GHz	-	-57	-	dBm
		1 GHz to 12 GHz	-	-47	-	dBm
Level above which RFSENSE will trigger	RFSENSE _{TRIG}	CW at 2.45 GHz	-	-17	-	dBm
Level below which RFSENSE wil not trigger	RFSENSE _{THRES}		-	-50	-	dBm

4.9.3 RF Transmitter Characteristics for Bluetooth Smart in the 2.4 GHz Band

Unless otherwise indicated T=25C,VREGVDD = AVDD = IOVDD = 3.3 V, DVDD = RFVDD = PAVDD. RFVDD and PAVDD path is filtered using ferrites. Crystal frequency=38.4MHz. RF center frequency 2.440 GHz. Test circuit according to Figure 5.2 EFR32MG1X232 Typical Application Circuit: Configuration with DC-DC Coverter (PAVDD from VDCDC) on page 44 and Figure 5.4 Typical 2.4 GHz RF impedance-matching network circuits on page 45.

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Transmit 6dB bandwidth	TXBW		-	TBD	-	kHz
Power spectral density limit	PSD _{LIMIT}	Per FCC part 15.247	-	TBD	-	dBm/ kHz
		Per ETSI 300.328	-	TBD	-	dBm/ MHz
Occupied channel bandwidth per ETSI EN300.328	OCP _{ETSI328}	99% BW at highest and lowest channels in band	-	TBD	-	MHz
In-band spurious emissions,	SPURINB	At ±2 MHz	-	-35	-	dBm
with allowed exceptions ¹		At ±3 MHz	-	-36	-	dBm
Emissions of harmonics out- of-band, per FCC part 15.247	SPUR _{HRM_FCC}	2nd,3rd, 5, 6, 8, 9,10 harmonics; continuous transmission of modu- lated carrier	-	TBD	-	dBm
Spurious emissions out-of- band, per FCC part 15.247, excluding harmonics cap- tured in SPUR _{HARM,FCC}	SPUR _{OOB_FCC}	Above 2.483 GHz or below 2.4 GHz; continuous transmission of modulated carrier	-	TBD	-	dBc
Spurious emissions out-of- band; per ETSI 300.328	SPUR _{ETSI328}	[2400-BW to 2400] MHz, [2483.5 to 2483.5+BW] MHz	-	TBD	-	dBm
		[2400-2BW to 2400-BW] MHz, [2483.5+BW to 2483.5+2BW] MHz per ETSI 300.328	Ċ	TBD	-	dBm
Spurious emissions per ETSI EN300.440	SPUR _{ETSI440}	47-74 MHz,87.5-108 MHz, 174-230 MHz, 470-862 MHz	-	TBD	-	nW
		25-1000 MHz	-	TBD	-	nW
		1-24 GHz	-	TBD	-	nW

Note:

1. Per Bluetooth Core_4.2, Section 3.2.2, exceptions are allowed in up to three bands of 1 MHz width, centered on a frequency which is an integer multiple of 1 MHz. These exceptions shall have an absolute value of -20 dBm or less.

4.9.4 RF Receiver Characteristics for Bluetooth Smart in the 2.4 GHz Band

Unless otherwise indicated T=25C,VREGVDD = AVDD = IOVDD = 3.3 V, DVDD = RFVDD = PAVDD. RFVDD and PAVDD path is filtered using ferrites. Crystal frequency=38.4MHz. RF center frequency 2.440 GHz. Test circuit according to Figure 5.2 EFR32MG1X232 Typical Application Circuit: Configuration with DC-DC Coverter (PAVDD from VDCDC) on page 44 and Figure 5.4 Typical 2.4 GHz RF impedance-matching network circuits on page 45.

Table 4.14. RF Receiver Characteristics for Bluetooth Smart in the 2.4GHz Band

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Max usable receiver input level, 0.1% BER	SAT	Signal is reference signal ¹ . Packet length is 20 bytes.	-	10	-	dBm
Sensitivity, 0.1% BER	SENS	Signal is reference signal. Using DC-DC converter ²	-	-94	-	dBm
		With dirty transmitter as defined in Core_4.1	-	-91.4	-	dBm
Signal to co-channel interfer- er, 0.1% BER	C/I _{CC}	Desired signal 3 dB above reference sensitivity	-	9	-	dB
N+1 adjacent channel (1 MHz) selectivity, 0.1% BER, with allowable exceptions ³ . Desired is reference signal at 3 dB above reference sensi- tivity level	C/I ₁₊	Interferer is reference signal at +1 MHz offset. Desired frequency 2402 MHz ≤ Fc ≤ 2480 MHz	-	-2	-	dB
N-1 adjacent channel (1 MHz) selectivity, 0.1% BER, with allowable exceptions ³ . Desired is reference signal at 3 dB above reference sensi- tivity level	C/I ₁₋	Interferer is reference signal at -1 MHz offset. Desired frequency 2402 MHz ≤ Fc ≤ 2480 MHz	-	0	-	dB
Alternate (2 MHz) selectivity, 0.1% BER, with allowable exceptions ³ . Desired is refer- ence signal at 3 dB above reference sensitivity level	C/I ₂	Interferer is reference signal at ± 2 MHz offset. Desired frequency 2402 MHz \leq Fc \leq 2480 MHz		-43	-	dB
Alternate (3 MHz) selectivity, 0.1% BER, with allowable exceptions ³ . Desired is refer- ence signal at 3 dB above reference sensitivity level	C/I ₃	Interferer is reference signal at ± 3 MHz offset. Desired frequency 2404 MHz \leq Fc \leq 2480 MHz		-48	-	dB
Selectivity to image frequen- cy, 0.1% BER. Desired is ref- erence signal at 3 dB above reference sensitivity level	C/I _{IM}	Interferer is reference signal at im- age frequency with 1 MHz preci- sion	-	-40		dB
Selectivity to image frequen- cy +1 MHz, 0.1% BER. ⁴ De- sired is reference signal at 3 dB above reference sensitivi- ty level	C/I _{IM+1}	Interferer is reference signal at im- age frequency +1 MHz with 1 MHz precision	-	-48	-	dB

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Blocking, 0.1% BER, Desired is reference signal at 3 dB above reference sensitivity level. Interferer is CW in OOB range.	BLOCK _{OOB}	Interferer frequency 30 MHz ≤ f ≤ 2000 MHz	-	-30	-	dBm
		Interferer frequency 2003 MHz ≤ f ≤ 2399 MHz	-	-35	-	dBm
		Interferer frequency 2484 MHz ≤ f ≤ 2997 MHz	-	-35	-	dBm
		Interferer frequency 3 GHz ≤ f ≤ 12.75 GHz	-	-30	-	dBm
Intermodulation performance per Core_4.1, Vol 6 Section 4.4 (n = 3 alternative), 0.1% BER.	IM	Desired is reference signal at 6dB above reference sensitivity level. Interferer 1 is CW at level IM_{BLE} . Interferer 2 is reference signal at IM_{BLE} .	-	-33	-	dBm
Upper limit of input power range over which RSSI reso- lution is maintained	RSSI _{MAX}		TBD	-	-	dBm
Lower limit of input power range over which RSSI reso- lution is maintained	RSSI _{MIN}		-	-	TBD	dBm
RSSI resolution	RSSI _{RES}	Over RSSI _{MIN} to RSSI _{MAX}	-	-	TBD	dB

Note:

1. Reference signal is defined in Core_4.2, Vol 6, Section 4.6. 2GFSK, Modulation index = 0.5, BT = 0.5, Bit rate = 1 Mbps, desired data = PRBS9; interferer data = PRBS15; frequency accuracy better than 1 ppm

2. Target for planned revision. Current silicon performance is -92.1 dBm

3. Allowable exceptions for spurious response RF channels, as specified in Core_4.2, Vol 6, Section 4.2 "Interference Performance". Where there is conflict of specifications regarding interference at image frequencies, the less stringent specification applies.

4. Selectivity to image frequency -1 MHz corresponds to C/I₁₊ N+1 adjacent hannel selectivity

4.9.5 RF Transmitter Characteristics for 802.15.4 O-QPSK DSSS in the 2.4 GHz Band

Unless otherwise indicated T=25C,VREGVDD = AVDD = IOVDD = 3.3 V, DVDD = RFVDD = PAVDD. RFVDD and PAVDD path is filtered using ferrites. Crystal frequency=38.4MHz. RF center frequency 2.445 GHz. Test circuit according to Figure 5.2 EFR32MG1X232 Typical Application Circuit: Configuration with DC-DC Coverter (PAVDD from VDCDC) on page 44 and Figure 5.4 Typical 2.4 GHz RF impedance-matching network circuits on page 45.

Table 4.15. RF Transmitter Characteristics for 802.15.4 DSSS-OQPSK in the 2.4GHz Band

Parameter	Symbol	Test Condition	Min	Тур	Мах	Unit
Error vector magnitude (off- set EVM), per 802.15.4-2011	EVM	Signal is DSSS-OQPSK reference packet ¹	-	5	-	% rms
Transmit center frequency error ²	FERR		-40	-	40	ppm
Power spectral density limit	PSD _{LIMIT}	Relative, at carrier ±3.5 MHz	-	TBD	-	dBc
		Absolute, at carrier ±3.5 MHz	-	TBD	-	dBm
		Per FCC part 15.247	-	TBD	-	dBm/kH z
		Per ETSI 300.328	-	TBD	-	dBm/M Hz
Occupied channel bandwidth per ETSI EN300.328	OCP _{ETSI328}	99% BW at highest and lowest channels in band	-	TBD	-	MHz
Emissions of harmonics out- of-band, per FCC part 15.247	SPUR _{HRM_FCC}	2nd,3rd, 5, 6,8,9,10 harmonics; continuous transmission of modu- lated carrier	-	TBD	-	dBm
Spurious emissions out-of- band, per FCC part 15.247, excluding harmonics	SPUR _{OOB_FCC}	Above 2.483 GHz or below 2.4 GHz; continuous transmission of modulated carrier	-	TBD	-	dBc
Spurious emissions out-of- band; per ETSI 300.328	SPUR _{ETSI328}	[2400-BW to 2400], [2483.5 to 2483.5+BW];		TBD	-	dBm
		[2400-2BW to 2400-BW], [2483.5+BW to 2483.5+2BW]; per ETSI 300.328		TBD	-	dBm
Spurious emissions per ETSI EN300.440	SPUR _{ETSI440}	47-74 MHz,87.5-108 MHz, 174-230 MHz, 470-862 MHz	•	TBD	-	nW
		25-1000 MHz,	-	TBD		nW
		1G-24G	-	TBD	-	nW

Note:

1. Reference packet is defined as TBD of packet length TBD, modulated according to 802.15.4-2011 DSSS-OQPSK in the 2.4GHz band, with pseudo-random packet data content

2. Frequency error measurements are referred to the high-frequency crystal reference of the device

4.9.6 RF Receiver Characteristics for 802.15.4 O-QPSK DSSS in the 2.4 GHz Band

Unless otherwise indicated T=25C,VREGVDD = AVDD = IOVDD = 3.3 V, DVDD = RFVDD = PAVDD. RFVDD and PAVDD path is filtered using ferrites. Crystal frequency=38.4MHz. RF center frequency 2.445 GHz. Test circuit according to Figure 5.2 EFR32MG1X232 Typical Application Circuit: Configuration with DC-DC Coverter (PAVDD from VDCDC) on page 44 and Figure 5.4 Typical 2.4 GHz RF impedance-matching network circuits on page 45.

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Max usable receiver input level, 1% PER	SAT	Signal is reference signal ¹ . Packet length is 20 octets.	-	10	-	dBm
Sensitivity, 1% PER	SENS	Signal is reference signal. Packet length is 20 octets. Using DC-DC converter.	-	-99.1	-	dBm
		Signal is reference signal. Packet length is 20 octets. Without DC- DC converter.	-	-99.4	-	dBm
Co-channel interferer rejec- tion, 1% PER	CCR	Desired signal 10 dB above sensi- tivity limit	-	-2.2	-	dB
High-side adjacent channel rejection, 1% PER. Desired	ACR+1	Interferer is reference signal at +1 channel-spacing.	-	34.1	-	dB
is reference signal at 3dB above reference sensitivity level ²		Interferer is filtered reference sig- nal ³ at +1 channel-spacing.	-	51	-	dB
		Interferer is CW at +1 channel- spacing. ⁴	-	58.7	-	dB
Low-side adjacent channel rejection, 1% PER. Desired	ACR ₋₁	Interferer is reference signal at -1 channel-spacing.	-	35.5	-	dB
is reference signal at 3dB above reference sensitivity level ²		Interferer is filtered reference sig- nal ³ at -1 channel-spacing.		54	-	dB
		Interferer is CW at -1 channel- spacing.		60.6	-	dB
Alternate channel rejection, 1% PER. Desired is refer-	ACR ₂	Interferer is reference signal at ±2 channel-spacing	-	45.6	-	dB
ence signal at 3dB above reference sensitivity level ²		Interferer is filtered reference sig- nal ³ at ±2 channel-spacing	-	59.5		dB
		Interferer is CW at ±2 channel- spacing	-	66	-	dB
Image rejection , 1% PER, Desired is reference signal at 3dB above reference sensi- tivity level ²	IR	Interferer is CW in image band ⁴	-	50.2	·	dB
Blocking rejection of all other channels. 1% PER, Desired	BLOCK	Interferer frequency < Desired fre- quency - 3 channel-spacing	-	58.8	-	dB
is reference signal at 3dB above reference sensitivity level ² . Interferer is reference signal.		Interferer frequency > Desired fre- quency + 3 channel-spacing	-	57.7	-	dB
Blocking rejection of 802.11g signal centered at +12MHz or -13MHz	BLOCK _{80211G}	Desired is reference signal at 6dB above reference sensitivity level ²	-	50.6	-	dB

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Upper limit of input power range over which RSSI reso- lution is maintained	RSSI _{MAX}		5	-	-	dBm
Lower limit of input power range over which RSSI reso- lution is maintained	RSSI _{MIN}		-	-	-98	dBm
RSSI resolution	RSSI _{RES}	over RSSI _{MIN} to RSSI _{MAX}	-	0.25	-	dB
RSSI linearity as defined by 802.15.4-2003	RSSI _{LIN}		-	TBD	-	dB

Note:

1. Reference signal is defined as TBD

2. Reference sensitivity level is -85 dBm

- 3. Filter is characterized as a symmetric bandpass centered on the adjacent channel having a 3dB bandwidth of 4.6 MHz and stopband rejection better than 26 dB beyond 3.15MHz from the adjacent carrier.
- 4. Due to low-IF frequency, there is some overlap of adjacent channel and image channel bands. Adjacent channel CW blocker tests place the Interferer center frequency at the Desired frequency ±5 MHz on the channel raster, whereas the image rejection test places the CW interferer near the image frequency of the Desired signal carrier, regardless of the channel raster.

4.10 RFSENSE

Table 4.17. RFSENSE

Parameter	Symbol	Test Condition	Min	Тур	Мах	Unit
RFSENSE current consump- tion	IRFSENSE		-	TBD	TBD	nA

4.11 Modem Features

Table 4.18. Modem Features

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Receive Bandwidth	RX _{Bandwidth}	Configurable range with 38.4 MHz crystal	0.1	-	2530	kHz
IF Frequency	IF _{Freq}	Configurable range with 38.4 MHz crystal. Selected steps available.	150	-	1371	kHz
DSSS symbol length	DSSS _{Range}	Configurable in steps of 1 chip	2	-	32	chips
DSSS Bits per symbol	DSSS _{BitPerSym}	Configurable	1	-	4	bits/ symbol

4.12 Oscillators

4.12.1 LFXO

Table 4.19. LFXO

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Crystal frequency	f _{LFXO}		-	32.768	-	kHz
Supported crystal equivalent series resistance (ESR)	ESR _{LFXO}		-	-	70	kΩ
Supported range of crystal load capacitance ¹	C _{LFXO_CL}		6	-	18	pF
On-chip tuning cap range ²	C _{LFXO_T}	On each of LFXTAL_N and LFXTAL_P pins	8	-	40	pF
On-chip tuning cap step size	SS _{LFXO}		-	0.25	-	pF
LFXO current consumption on AVDD ³ after startup	ILFXO_ANA	ESR = 30 kΩ, C _L =12.5 pF, GAIN ⁴ = 3, AGC ⁴ = 1	-	TBD	-	nA
LFXO current consumption on DVDD after startup	ILFXO_DIG	ESR = 30 kΩ, C _L =12.5 pF, GAIN ⁴ = 1	-	TBD	-	nA
Start- up time	t _{LFXO}	ESR=30 kΩ, C _L =12.5 pF, GAIN ⁴ =2	-	200	-	ms

Note:

1. Total load capacitance as seen by the crystal

 The effective load capacitance seen by the crystal will be C_{LFXO_T} /2. This is because each XTAL pin has a tuning cap and the two caps will be seen in series by the crystal.

3. Current consumption on DVDD instead if ANASW=1 in EMU_PWRCTRL register

4. In CMU_LFXOCTRL register

Table 4.20. HFXO

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Crystal Frequency	f _{HFXO}		38	38.4	40	MHz
Supported crystal equivalent series resistance (ESR)	ESR _{HFXO}	Crystal frequency 38.4 MHz	-	-	60	Ω
Supported range of crystal load capacitance ¹	C _{HFXO_CL}		6	-	12	pF
On-chip tuning cap range ²	C _{HFXO_T}	On each of HFXTAL_N and HFXTAL_P pins	0	20	25	pF
On-chip tuning capacitance step	SS _{HFXO}		-	0.04	-	pF
Current consumption on DVDD for HFXO after startup	I _{HFXODIG}	38.4 MHz: ESR = 50 Ω, C_L = 10 pF, BOOST ³ = 2	-	TBD	-	μA
Current consumption on AVDD for HFXO after startup	Ihfxoana	38.4 MHz: ESR = 50 Ω, C_L = 10 pF, BOOST ³ = 2	-	TBD	-	μA
Startup time	t _{HFXO}	38.4 MHz: ESR=50 Ω, C_L = 10 pF, BOOST ³ = 2	-	300	-	μs
Frequency Tolerance for the crystal	FT _{HFXO}	38.4 MHz, ESR = 50 Ω, CL = 10 pF	-40	-	40	ppm

Note:

1. Total load capacitance as seen by the crystal

 The effective load capacitance seen by the crystal will be C_{HFXO_T} /2. This is because each XTAL pin has a tuning cap and the two caps will be seen in series by the crystal.

3. In CMU_HFXOCTRL register

4.12.3 LFRCO

Table 4.21. LFRCO

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Oscillation frequency	f _{LFRCO}		TBD	32.768	TBD	kHz
Startup time	t _{LFRCO}		-	500	-	μs
Current consumption on DVDD	ILFRCODIG	_	-	TBD	-	nA
Current consumption on AVDD ¹	I _{LFRCOANA}		-	TBD	-	nA
Note:	, ,			1	1	
1. Current consumption o	n DVDD instead if A	ANASW=1 in EMU_PWRCTRL registed	er			

4.12.4 HFRCO and AUXHFRCO

Oscillation frequency		Test Condition	Min	Тур	Max	Unit
	f _{HFRCO}	38 MHz frequency band	TBD	38	TBD	MHz
		32 MHz frequency band	TBD	D 38 TBD D 32 TBD D 26 TBD D 19 TBD D 19 TBD D 16 TBD D 13 TBD D 13 TBD D 13 TBD D 4 TBD D 4 TBD D 2 TBD D 1 TBD D 1 TBD D 1 - 300 - - 1 - - 2.5 - - TBD - -	MHz	
		26 MHz frequency band	TBD	26	TBD	MHz
		19 MHz frequency band	TBD	19	TBD	MHz
		16 MHz frequency band	TBD	16	TBD	MHz
		13 MHz frequency band	TBD	13	TBD	MHz
		7 MHz frequency band	TBD	7	TBD	MHz
		4 MHz frequency band	TBD	4	TBD	MHz
		2 MHz frequency band	TBD	2	TBD	MHz
		1 MHz frequency band	TBD	1	TBD	MHz
Start-up time	t _{HFRCO}	f _{HFRCO} ≥ 19 MHz	-	300	-	ns
		4 < f _{HFRCO} < 19 MHz	-	1	-	μs
		f _{HFRCO} ≤ 4 MHz	-	2.5	-	μs
Current consumption on	I _{HFRCODIG}	f _{HFRCO} = 38 MHz	-	TBD	-	μA
DVDD		f _{HFRCO} = 32 MHz	-	TBD	-	μA
		f _{HFRCO} = 26 MHz	-	TBD	-	μA
		f _{HFRCO} = 19 MHz	-	TBD	TBD	μA
		f _{HFRCO} = 16 MHz	-	TBD	-	μA
		f _{HFRCO} = 13 MHz		TBD	-	μA
		f _{HFRCO} = 7 MHz	-	TBD	-	μA
		f _{HFRCO} = 4 MHz	-	TBD	-	μA
		f _{HFRCO} = 2 MHz	-	TBD	-	μA
		f _{HFRCO} = 1 MHz	-	TBD	-	μΑ
Current consumption on	I _{HFRCOANA}	f _{HFRCO} = 38 MHz	-	TBD	-	μA
AVDD ¹		f _{HFRCO} = 32 MHz	-	TBD	-	μA
		f _{HFRCO} = 26 MHz	-	TBD	-	μA
		f _{HFRCO} = 19 MHz	-	TBD	TBD	μΑ
		f _{HFRCO} = 16 MHz	-	TBD	-	μΑ
		f _{HFRCO} = 13 MHz	-	TBD	-	μA
		f _{HFRCO} = 7 MHz	-	TBD	-	μA
		f _{HFRCO} = 4 MHz	-	TBD	-	μA
		f _{HFRCO} = 2 MHz	-	TBD	-	μA
		f _{HFRCO} = 1 MHz	_	TBD	-	μA

Table 4.22. HFRCO and AUXHFRCO

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Step size	SS _{HFRCO}	Coarse (% of period)	-	0.8	-	%
		Fine (% of period)	-	0.1	-	%
Duty cycle	DC _{HFRCO}		47.5	-	52.5	%
Period Jitter	PJ _{HFRCO}		-	0.2	-	% RMS
Note: 1. Current consum	ption on DVDD instead i	f ANASW=1 in EMU_PWRCTRL re	egister	1	1	_1

4.12.5 ULFRCO

Table 4.23. ULFRCO

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Oscillation frequency	f _{ULFRCO}		TBD	1	TBD	kHz

Table 4.24. GPIO

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Input low voltage	V _{IOIL}		-	-	IOVDD*0.3	V
Input high voltage	VIOIH		IOVDD*0.7	-	-	V
Output high voltage relative to IOVDD	V _{IOOH}	Sourcing 3 mA, $V_{DD} \ge 3 V$, DRIV- ESTRENGTH ¹ = WEAK	IOVDD*0.8	-	-	V
		Sourcing 1.2 mA, $V_{DD} \ge 1.62$ V, DRIVESTRENGTH ¹ = WEAK	IOVDD*0.6	-	-	V
		Sourcing 20 mA, $V_{DD} \ge 3 V$, DRIV- ESTRENGTH ¹ = STRONG	IOVDD*0.8	-	-	V
		Sourcing 8 mA, $V_{DD} \ge 1.62 V$, DRIVESTRENGTH ¹ = STRONG	IOVDD*0.6	-	-	V
Output low voltage relative to IOVDD	V _{IOOL}	Sinking 3 mA, $V_{DD} \ge 3 V$, DRIV- ESTRENGTH ¹ = WEAK	-	-	IOVDD*0.2	V
		Sinking 1.2 mA, $V_{DD} \ge 1.62$ V, DRIVESTRENGTH ¹ = WEAK	-	-	IOVDD*0.4	V
		Sinking 20 mA, $V_{DD} \ge 3$ V, DRIV- ESTRENGTH ¹ = STRONG	-	-	IOVDD*0.2	V
		Sinking 8 mA, $V_{DD} \ge 1.62 V$, DRIVESTRENGTH ¹ = STRONG	-	-	IOVDD*0.4	V
Input leakage current	I _{IOLEAK}	GPIO ≤ IOVDD	-	0.1	TBD	nA
Input leakage current on 5VTOL pads above IOVDD	I _{5VTOLLEAK}	IOVDD < GPIO ≤ IOVDD + 2 V		3.3	15	μA
I/O pin pull-up resistor	R _{PU}		TBD	40	TBD	kΩ
I/O pin pull-down resistor	R _{PD}		TBD	40	TBD	kΩ
Pulse width of pulses re- moved by the glitch suppres- sion filter	t _{IOGLITCH}		TBD	25	TBD	ns
Output fall time, From 70% to 30% of V _{IO}	t _{IOOF}	C _L = 50pF, DRIVESTRENGTH ¹ = STRONG, SLEWRATE ¹ = 0x6	-	TBD	-	ns
		C_L = 50pF, DRIVESTRENGTH ¹ = WEAK, SLEWRATE ¹ = 0x6	-	TBD	-	ns
Output rise time, From 30% to 70% of V _{IO}	t _{IOOR}	C _L = 50pF, DRIVESTRENGTH ¹ = STRONG, SLEWRATE = 0x6 ¹	-	TBD	-	ns
		$C_L = 50 pF, DRIVESTRENGTH^1 = WEAK, SLEWRATE^1 = 0x6$	-	TBD	-	ns

1. In GPIO_Pn_CTRL register
Table 4.25. VMON

Parameter	Symbol	Test Condition	Min	Тур	Мах	Unit
VMON Supply Current in EM0 or EM1	I _{VMON}	In EM0 or EM1, 1 supply moni- tored	-	5.8	-	μA
		In EM0 or EM1, 4 supplies moni- tored	-	11.8	-	μA
		In EM2, EM3 or EM4, 1 supplies monitored	-	68	-	nA
		In EM2, EM3 or EM4, 4 supplies monitored	-	115	-	nA
VMON Loading of Monitored	ISENSE	In EM0 or EM1	-	2	-	μA
Supply		In EM2, EM3 or EM4	-	2	-	nA
Threshold range	V _{VMON_RANGE}		TBD	-	TBD	V
Threshold step size	N _{VMON_STESP}	Coarse	-	200	-	mV
		Fine	-	20	-	mV
Response time	t _{VMON_RES}	Supply drops at 1V/µs rate	-	500	-	ns
Hysteresis	Vvmon_hyst		-	TBD	-	mV

Table 4.26. ADC

Parameter	Symbol	Test Condition	Min	Тур	Мах	Unit
Resolution	solution V _{RESOLUTION}		6	-	12	Bits
Input voltage range	VADCIN	Single ended	0	-	2*V _{REF}	V
		Differential	-V _{REF}	-	V _{REF}	V
Input range of external refer- ence voltage, single ended and differential	VADCREFIN_P		1	-	V _{AVDD}	V
Power supply rejection	PSRR _{ADC}	At DC	-	80	-	dB
Analog input common mode rejection ratio	CMRR _{ADC}	At DC	-	80	-	dB
Current on DVDD, using in-	IADCDIG_CONTI-	1 Msps / 16 MHz ADCCLK,	-	TBD	-	μA
ternal reference buffer. Con- tinous operation. WARMUP- MODE ¹ = KEEPADCWARM	NOUS	$BIASPROG^2 = 0$				
		250 ksps / 4 MHz ADCCLK, BIA- SPROG ² = 6	-	TBD	-	μA
		62.5 Msps / 1 MHz ADCCLK,	-	TBD	-	μA
		BIASPROG ² = 15				
Current on DVDD, using in-	I _{ADCDIG_NORMAL}	50 ksps / 16 MHz ADCCLK,	-	TBD	-	μA
ternal reference buffer. Duty- cycled operation. WARMUP-		BIASPROG ² = 0				
MODE ¹ = NORMAL		5 ksps / 16 MHz ADCCLK	-	TBD	-	μA
		BIASPROG ² = 0				
Current on DVDD, using in-	IADCDIG_STAND-	125 ksps / 16 MHz ADCCLK,	-	TBD	-	μA
ternal reference buffer. Duty- cycled operation. AWAR-	BY	BIASPROG ² = 0				
MUPMODE ¹ = KEEPIN- STANDBY or KEEPINSLO-		5 ksps / 16 MHz ADCCLK,	-	TBD	-	μA
WACC		BIASPROG ² = 0				
Current on AVDD ³ , using in-	I _{ADCANA_CONTI-}	1 Msps / 16 MHz ADCCLK,	-	TBD		μA
ternal reference buffer. Con- tinous operation. WARMUP-	NOUS	BIASPROG ² = 0				
MODE ¹ = KEEPADCWARM		250 ksps / 4 MHz ADCCLK, BIA- SPROG ² = 6	-	TBD	-	μA
		62.5 Msps / 1 MHz ADCCLK,	-	TBD	-	μA
		BIASPROG ² = 15				
Current on AVDD ³ , using in-	IADCANA_NORMAL	50 Ksps / 16 MHz ADCCLK,	-	TBD	-	μA
ternal reference buffer. Duty- cycled operation. WARMUP-		BIASPROG ² = 0				
MODE ¹ = NORMAL		5 Ksps / 16 MHz ADCCLK,	-	TBD	-	μA
		BIASPROG ² = 0				

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Current on AVDD ³ , using in- ternal reference buffer. Duty-	I _{ADCANA_STAND-}	125 Ksps / 16 MHz ADCCLK,	-	TBD	-	μA
cycled operation. WARMUP-	ВХ	BIASPROG ² = 0				
MODE ¹ = KEEPINSTANDBY or KEEPINSLOWACC		5 Ksps / 16 MHz ADCCLK,	-	TBD	-	μA
		BIASPROG ² = 0				
ADC Clock Frequency	fadcclk		-	-	16	MHz
Throughput rate	f ADCRATE		-	-	1	Msps
Conversion time	tadcconv	6 bit	-	7	-	ADCC K Cy- cles
		10 bit	-	11	-	ADCC K Cy- cles
		12 bit	-	13	-	ADCC K Cy- cles
Startup time of reference generator and ADC core in NORMAL mode	tadcstart	WARMUPMODE ¹ = NORMAL	-	-	5	μs
From standby mode		WARMUPMODE ¹ = KEEPIN- STANDBY or KEEPINSLOWACC	-	-	1	μs
SNDR at 1Msps and f _{in} = 10kHz	SNDR _{ADC}	Internal reference, 2.5 V full-scale, differential (-1.25, 1.25)	TBD	67	-	dB
		vrefp_in = 1.25 V direct mode with 2.5 V full-scale, differential	-	68	-	dB
Spurious-Free Dynamic Range (SFDR)	SFDR _{ADC}	1 MSamples/s, 10 kHz full-scale sine wave		75	-	dB
nput referred ADC noise, ms	V _{REF_NOISE}	Including quantization noise and distortion		380	-	μV
Offset Error	VADCOFFSETERR		TBD	1	TBD	LSB
Gain error in ADC	V _{ADC_GAIN}	Using internal reference	-	±0.1	TBD	%
		Using external reference	-	TBD		%
Differential non-linearity DNL)	DNL _{ADC}	12 bit resolution	-1		TBD	LSB
ntegral non-linearity (INL),	INL _{ADC}	12 bit resolution	TBD	-	TBD	LSB

3. Current consumption on DVDD instead if ANASW=1 in EMU_PWRCTRL register

Table 4.27. IDAC

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Number of Ranges	N _{IDAC_RANGES}		-	4	-	-
Output Current	IDAC_OUT	RANGSEL ¹ = RANGE0	0.05	-	1.6	μA
		RANGSEL ¹ = RANGE1	1.6	-	4.7	μA
		RANGSEL ¹ = RANGE2	0.5	-	16	μA
		RANGSEL ¹ = RANGE3	2	-	64	μA
Linear steps within each range	N _{IDAC_STEPS}		-	32	-	
Step size	SSIDAC	RANGSEL ¹ = RANGE0	-	50	-	nA
		RANGSEL ¹ = RANGE1	-	100	-	nA
		RANGSEL ¹ = RANGE2	-	500	-	nA
		RANGSEL ¹ = RANGE3	-	2	-	μA
Total Accuracy, STEPSEL ¹ = 0x10	ACC _{IDAC}	Continuous mode, AVDD=3.3V, T = 25°C	TBD	-	TBD	%
		Continuous mode, AVDD=3.8V, across all temperature	TBD	-	TBD	%
		EM2 or EM3	TBD	-	TBD	%
Start up time	t _{IDAC_SU}	Output within 1% of steady state value	-	5	TBD	μs
Settling time, (output settled	t _{IDAC_SETTLE}	Range setting is changed	-	5	-	μs
within 1% of steady state value)		Step value is changed	-	1	-	μs
Current consumption on AVDD in continuous mode ²	I _{IDAC}	Source mode, excluding output current	-	9.2	-	μΑ
		Sink mode, excluding output cur- rent	-	12.3	-	μA
Output voltage compliance in source mode, source current change relative to current sourced at 0 V	ICOMP_SRC	RANGESEL1=0, output voltage = max(V(IOVDD), V(AVDD) ³ -100 m v)	-	TBD	-	%
		RANGESEL1=1, output voltage = max(V(IOVDD), V(AVDD) ³ -100 m V)	-	TBD	-	%
		RANGESEL1=2, output voltage = max(V(IOVDD), V(AVDD) ³ -150 m V)	-	TBD	-	%
		RANGESEL1=3, output voltage = max(V(IOVDD), V(AVDD) ³ -250 m V)	-	TBD	-	%

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Output voltage compliance in source mode, sink current change relative to current sunk at IOVDD	I _{COMP_SINK}	RANGESEL1=0, output voltage = 100 mV	-	TBD	-	%
	10 R 15 R	RANGESEL1=1, output voltage = 100 mV	-	TBD	-	%
		RANGESEL1=2, output voltage = 150 mV	-	TBD	-	%
		RANGESEL1=3, output voltage = 250 mV	-	TBD	-	%

Note:

- 1. In IDAC_CURPROG register
- 2. Current consumption on DVDD instead if ANASW=1 in EMU_PWRCTRL register
- 3. Voltage reference AVDD switches to DVDD when ANASW=1 in EMU_PWRCTRL

4.17 Analog Comparator (ACMP)

Table 4.28. ACMP

Parameter	Symbol	Test Condition	Min	Тур	Мах	Unit
Input voltage range	V _{ACMPIN}	CMPVDD = ACMPn_CTRL_PWRSEL ¹	0	-	CMPVDD	V
Active current not including	IACMP	$BIASPROG^2 = 1$, $FULLBIAS^2 = 0$	-	50	-	nA
voltage reference		$BIASPROG^{2} = 0x10, FULLBIAS^{2}$ $= 0$	-	370	TBD	nA
		BIASPROG ² = 0x20, FULLBIAS ² = 1	-	65	TBD	μA
Current consumption of inter- nal voltage reference,	IACMPREF	VLP selected as input using 2.5V Reference / 4 (0.625V)	-	50	-	nA
		VLP selected as input using VDD	-	20	-	nA
		VBDIV selected as input using 1.25 V reference / 1	-	3	-	μA
		VADIV selected as input using VDD/1	-	2	-	μA
Hysteresis	V _{ACMPHYST}	HYSTSEL ³ = HYST0	-	0	TBD	mV
		HYSTSEL ³ = HYST1	-	14	-	mV
		HYSTSEL ³ = HYST2		25	-	mV
		HYSTSEL ³ = HYST3	-	30	-	mV
		HYSTSEL ³ = HYST4	-	35	-	mV
		HYSTSEL ³ = HYST5		39	-	mV
		HYSTSEL ³ = HYST6	· · ·	42	-	mV
		HYSTSEL ³ = HYST7	-	45	-	mV
Comparator delay	t _{ACMPDELAY}	$BIASPROG^2 = 1, FULLBIAS^2 = 0$		30	-	μs
		BIASPROG ² = 0×10 , FULLBIAS ² = 0^{4}	-	3.7		μs
		BIASPROG ² = 0x20, FULLBIAS ² = 1 ⁴	-	35	-	ns
Startup time of reference generator	t _{ACMPREF}	BIASPROG ² =0x07, FULLBIAS ² = 1 ⁴	-	TBD		μs
Offset voltage	VACMPOFFSET		-	-	TBD	mV

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Reference Voltage	V _{ACMPREF}	Single ended, internal 1.25 V reference	TBD	1.25	TBD	V
		Single ended, internal 2.5 V reference	TBD	2.5	TBD	V
		Differential, internal 1.25 V reference	TBD	1.25	TBD	V
		Differential, internal 2.5 V reference	TBD	2.5	TBD	V
Capacitive Sense Internal Resistance	nal R _{CSRES}	CSRESSEL ⁵ = 0	-	inf	-	kΩ
Resistance		CSRESSEL ⁵ = 1	-	12	-	kΩ
		CSRESSEL ⁵ = 2	-	24	-	kΩ
		CSRESSEL ⁵ = 3	-	36	-	kΩ
		CSRESSEL ⁵ = 4	-	48	-	kΩ
		CSRESSEL ⁵ = 5	-	92	-	kΩ
		CSRESSEL ⁵ = 6	-	148	-	kΩ
		CSRESSEL ⁵ = 7	-	215	-	kΩ

Note:

1. CMPVDD is a supply chosen by the setting in ACMPn_CTRL_PWRSEL and may be IOVDD, AVDD or DVDD

2. In ACMPn_CTRL register

3. In ACMPn_HYSTERESIS register

- 4. ± 100 mV differential
- 5. In ACMPn_INPUTSEL register

The total ACMP current is the sum of the contributions from the ACMP and its internal voltage reference as given as:

I_{ACMPTOTAL} = I_{ACMP} + I_{ACMPREF}

I_{ACMPREF} is zero if an external voltage reference is used.

5. Application Circuits

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5.1 Power Supplies

Typical power supply connections for direct supply, without using the internal DC-DC converter, are shown in the following figure.



Figure 5.1. EFR32MG1X232 Typical Application Circuit: Direct Supply Configuration without DC-DC converter

Typical power supply circuits using the internal DC-DC converter are shown below. The MCU operates from the DC-DC converter supply. For low RF transmit power applications less than 13dBm, the RF PA may be supplied by the DC-DC converter. For OPNs supporting high power RF transmission, the RF PA must be directly supplied by VDD for RF transmit power greater than 13 dBm.



Figure 5.2. EFR32MG1X232 Typical Application Circuit: Configuration with DC-DC Coverter (PAVDD from VDCDC)





5.2 RF Matching Networks

Typical RF matching network circuit diagrams are shown in Figure 5.4 Typical 2.4 GHz RF impedance-matching network circuits on page 45 for applications in the 2.4GHz band. Application-specific component values can be found in the EFR32 Reference Manual. For low RF transmit power applications less than 13dBm, the two-element match is recommended. For OPNs supporting high power RF transmission, the four-element match is recommended for high RF transmit power (> 13dBm).





6. Pinout and Package

6.1 Pinout

The EFR32MG1X232 pinout, including selected functionality, is shown in Figure 6.1 EFR32MG1X232 Pinout (top view, not to scale) on page 46.



Figure 6.1. EFR32MG1X232 Pinout (top view, not to scale)

Table 6.1. Device Pinout

Q	-N48 Pin# and		Pin Altern	ate Functionality / D	QFN48 Pin# and Pin Alternate Functionality / Description								
	Name												
Pin #	Pin Name	Analog	Timers	Communication	Radio	Other							
0	VSSIO_0_0	GroundIO_0_0											
1	PF0	BUSBY BUSAX	TIM0_CC0 #24 TIM0_CC1 #23 TIM0_CC2 #22 TIM0_CDT10 #21 TIM0_CDT11 #20 TIM0_CDT12 #19 TIM1_CC0 #24 TIM1_CC1 #23 TIM1_CC2 #22 TIM1_CC3 #21 LE- TIM0_OUT0 #24 LETIM0_OUT1 #23 PCNT0_S0IN #24 PCNT0_S1IN #23	US0_TX #24 US0_RX #23 US0_CLK #22 US0_CS #21 US0_CTS #20 US0_RTS #19 US1_TX #24 US1_RX #23 US1_CLK #22 US1_CS #21 US1_CTS #20 US1_RTS #19 LEU0_TX #24 LEU0_RX #23 I2C0_SDA #24 I2C0_SCL #23	FRC_DCLK #24 FRC_DOUT #23 FRC_DFRAME #22 MODEM_DCLK #24 MODEM_DIN #23 MODEM_DOUT #22 MODEM_ANT0 #21 MODEM_ANT1 #20	PRS_CH0 #0 PRS_CH1 #7 PRS_CH2 #6 PRS_CH3 #5 ACMP0_O #24 ACMP1_O #24 DBG_SWCLKTCK #0 BOOT_TX							
2	PF1	BUSAY BUSBX	TIM0_CC0 #25 TIM0_CC1 #24 TIM0_CC2 #23 TIM0_CDTI0 #22 TIM0_CDTI1 #21 TIM0_CDTI2 #20 TIM1_CC0 #25 TIM1_CC1 #24 TIM1_CC2 #23 TIM1_CC3 #22 LE- TIM0_OUT0 #25 LETIM0_OUT1 #24 PCNT0_S0IN #25 PCNT0_S1IN #24	US0_TX #25 US0_RX #24 US0_CLK #23 US0_CS #22 US0_CTS #21 US0_RTS #20 US1_TX #25 US1_RX #24 US1_CLK #23 US1_CS #22 US1_CTS #21 US1_RTS #20 LEU0_TX #25 LEU0_RX #24 I2C0_SDA #25 I2C0_SCL #24	FRC_DCLK #25 FRC_DOUT #24 FRC_DFRAME #23 MODEM_DCLK #25 MODEM_DIN #24 MODEM_DOUT #23 MODEM_ANT0 #22 MODEM_ANT1 #21	PRS_CH0 #1 PRS_CH1 #0 PRS_CH2 #7 PRS_CH3 #6 ACMP0_O #25 ACMP1_O #25 DBG_SWDIOTMS #0 BOOT_RX							

QI	FN48 Pin# and Name	and Pin Alternate Functionality / Description						
Pin #	Pin Name	Analog	Timers	Communication	Radio	Other		
3	PF2	BUSBY BUSAX	TIM0_CC0 #26 TIM0_CC1 #25 TIM0_CC2 #24 TIM0_CDTI0 #23 TIM0_CDTI1 #22 TIM0_CDTI2 #21 TIM1_CC0 #26 TIM1_CC1 #25 TIM1_CC2 #24 TIM1_CC3 #23 LE- TIM0_OUT0 #26 LETIM0_OUT1 #25 PCNT0_S0IN #26 PCNT0_S1IN #25	US0_TX #26 US0_RX #25 US0_CLK #24 US0_CS #23 US0_CTS #22 US0_RTS #21 US1_TX #26 US1_RX #25 US1_CLK #24 US1_CS #23 US1_CTS #22 US1_RTS #21 LEU0_TX #26 LEU0_RX #25 I2C0_SDA #26 I2C0_SCL #25	FRC_DCLK #26 FRC_DOUT #25 FRC_DFRAME #24 MODEM_DCLK #26 MODEM_DIN #25 MODEM_DOUT #24 MODEM_ANT0 #23 MODEM_ANT1 #22	CMU_CLK0 #6 PRS_CH0 #2 PRS_CH1 #1 PRS_CH2 #0 PRS_CH3 #7 ACMP0_O #26 ACMP1_O #26 DBG_TDO #0 DBG_SWO #0 GPIO_EM4WU0		
4	PF3	BUSAY BUSBX	TIM0_CC0 #27 TIM0_CC1 #26 TIM0_CC2 #25 TIM0_CDTI0 #24 TIM0_CDTI1 #23 TIM0_CDTI2 #22 TIM1_CC0 #27 TIM1_CC1 #26 TIM1_CC2 #25 TIM1_CC3 #24 LE- TIM0_OUT0 #27 LETIM0_OUT1 #26 PCNT0_S0IN #27 PCNT0_S1IN #26	US0_TX #27 US0_RX #26 US0_CLK #25 US0_CS #24 US0_CTS #23 US0_RTS #22 US1_TX #27 US1_RX #26 US1_CLK #25 US1_CS #24 US1_CTS #23 US1_RTS #22 LEU0_TX #27 LEU0_RX #26 I2C0_SDA #27 I2C0_SCL #26	FRC_DCLK #27 FRC_DOUT #26 FRC_DFRAME #25 MODEM_DCLK #27 MODEM_DIN #26 MODEM_DOUT #25 MODEM_ANT0 #24 MODEM_ANT1 #23	CMU_CLK1 #6 PRS_CH0 #3 PRS_CH1 #2 PRS_CH2 #1 PRS_CH3 #0 ACMP0_O #27 ACMP1_O #27 DBG_TDI #0		
5	PF4	BUSBY BUSAX	TIM0_CC0 #28 TIM0_CC1 #27 TIM0_CC2 #26 TIM0_CDTI0 #25 TIM0_CDTI1 #24 TIM0_CDTI2 #23 TIM1_CC0 #28 TIM1_CC1 #27 TIM1_CC2 #26 TIM1_CC3 #25 LE- TIM0_OUT0 #28 LETIM0_OUT1 #27 PCNT0_S0IN #28 PCNT0_S1IN #27	US0_TX #28 US0_RX #27 US0_CLK #26 US0_CS #25 US0_CTS #24 US0_RTS #23 US1_TX #28 US1_RX #27 US1_CLK #26 US1_CS #25 US1_CTS #24 US1_RTS #23 LEU0_TX #28 LEU0_RX #27 I2C0_SDA #28 I2C0_SCL #27	FRC_DCLK #28 FRC_DOUT #27 FRC_DFRAME #26 MODEM_DCLK #28 MODEM_DIN #27 MODEM_DIN #27 MODEM_DOUT #26 MODEM_ANT0 #25 MODEM_ANT1 #24	PRS_CH0 #4 PRS_CH1 #3 PRS_CH2 #2 PRS_CH3 #1 ACMP0_O #28 ACMP1_O #28		

QF	N48 Pin# and Name		Pin Altern	ate Functionality / D	escription	
Pin #	Pin Name	Analog	Timers	Communication	Radio	Other
6	PF5	BUSAY BUSBX	TIM0_CC0 #29 TIM0_CC1 #28 TIM0_CC2 #27 TIM0_CDTI0 #26 TIM0_CDTI1 #25 TIM0_CDTI2 #24 TIM1_CC0 #29 TIM1_CC1 #28 TIM1_CC2 #27 TIM1_CC3 #26 LE- TIM0_OUT0 #29 LETIM0_OUT1 #28 PCNT0_S0IN #29 PCNT0_S1IN #28	US0_TX #29 US0_RX #28 US0_CLK #27 US0_CS #26 US0_CTS #25 US0_RTS #24 US1_TX #29 US1_RX #28 US1_CLK #27 US1_CS #26 US1_CTS #25 US1_RTS #24 LEU0_TX #29 LEU0_RX #28 I2C0_SDA #29 I2C0_SCL #28	FRC_DCLK #29 FRC_DOUT #28 FRC_DFRAME #27 MODEM_DCLK #29 MODEM_DIN #28 MODEM_DOUT #27 MODEM_ANT0 #26 MODEM_ANT1 #25	PRS_CH0 #5 PRS_CH1 #4 PRS_CH2 #3 PRS_CH3 #2 ACMP0_O #29 ACMP1_O #29
7	PF6	BUSBY BUSAX	TIM0_CC0 #30 TIM0_CC1 #29 TIM0_CC2 #28 TIM0_CDTI0 #27 TIM0_CDTI1 #26 TIM0_CDTI2 #25 TIM1_CC0 #30 TIM1_CC1 #29 TIM1_CC2 #28 TIM1_CC3 #27 LE- TIM0_OUT0 #30 LETIM0_OUT1 #29 PCNT0_S0IN #30 PCNT0_S1IN #29	US0_TX #30 US0_RX #29 US0_CLK #28 US0_CS #27 US0_CTS #26 US0_RTS #25 US1_TX #30 US1_RX #29 US1_CLK #28 US1_CS #27 US1_CTS #26 US1_RTS #25 LEU0_TX #30 LEU0_RX #29 I2C0_SDA #30 I2C0_SCL #29	FRC_DCLK #30 FRC_DOUT #29 FRC_DFRAME #28 MODEM_DCLK #30 MODEM_DIN #29 MODEM_DOUT #28 MODEM_ANT0 #27 MODEM_ANT1 #26	CMU_CLK1 #7 PRS_CH0 #6 PRS_CH1 #5 PRS_CH2 #4 PRS_CH3 #3 ACMP0_O #30 ACMP1_O #30
8	PF7	BUSAY BUSBX	TIM0_CC0 #31 TIM0_CC1 #30 TIM0_CC2 #29 TIM0_CDTI0 #28 TIM0_CDTI1 #27 TIM0_CDTI2 #26 TIM1_CC0 #31 TIM1_CC1 #30 TIM1_CC2 #29 TIM1_CC3 #28 LE- TIM0_OUT0 #31 LETIM0_OUT1 #30 PCNT0_S0IN #31 PCNT0_S1IN #30	US0_TX #31 US0_RX #30 US0_CLK #29 US0_CS #28 US0_CTS #27 US0_RTS #26 US1_TX #31 US1_RX #30 US1_CLK #29 US1_CS #28 US1_CTS #27 US1_RTS #26 LEU0_TX #31 LEU0_RX #30 I2C0_SDA #31 I2C0_SCL #30	FRC_DCLK #31 FRC_DOUT #30 FRC_DFRAME #29 MODEM_DCLK #31 MODEM_DIN #30 MODEM_DOUT #29 MODEM_ANT0 #28 MODEM_ANT1 #27	CMU_CLK0 #7 PRS_CH0 #7 PRS_CH1 #6 PRS_CH2 #5 PRS_CH3 #4 ACMP0_O #31 ACMP1_O #31 GPIO_EM4WU1
9	RFVDD	Radio power supply	·			
10	HFXTAL_N	High Frequency Crys	tal input pin.			
11	HFXTAL_P	High Frequency Crys	tal output pin.			
12	RESETn		w.To apply an external internal pull-up ensure		n, it is required to only d	Irive this pin low dur-
13	NC	No Connect.				

QF	N48 Pin# and Name		Pin Altern	nate Functionality / Description				
Pin #	Pin Name	Analog	Timers	Communication	Radio	Other		
14	RFVSS	Radio Ground						
15	PAVSS	Power Amplifier (PA)	voltage regulator VSS					
16	2G4RF_ION	2.4 GHz Differential F	RF input/output, negativ	e path.				
17	2G4RF_IOP	2.4 GHz Differential F	RF input/output, positive	e path.				
18	PAVDD	Power Amplifier (PA)	voltage regulator VDD	input				
19	PD10	BUSDY BUSCX	TIM0_CC0 #18 TIM0_CC1 #17 TIM0_CC2 #16 TIM0_CDTI0 #15 TIM0_CDTI1 #14 TIM0_CDTI2 #13 TIM1_CC0 #18 TIM1_CC1 #17 TIM1_CC2 #16 TIM1_CC3 #15 LE- TIM0_OUT0 #18 LETIM0_OUT1 #17 PCNT0_S0IN #18 PCNT0_S1IN #17	US0_TX #18 US0_RX #17 US0_CLK #16 US0_CS #15 US0_CTS #14 US0_RTS #13 US1_TX #18 US1_RX #17 US1_CLK #16 US1_CS #15 US1_CTS #14 US1_RTS #13 LEU0_TX #18 LEU0_RX #17 I2C0_SDA #18 I2C0_SCL #17	FRC_DCLK #18 FRC_DOUT #17 FRC_DFRAME #16 MODEM_DCLK #18 MODEM_DIN #17 MODEM_DOUT #16 MODEM_ANT0 #15 MODEM_ANT1 #14	CMU_CLK1 #4 PRS_CH3 #9 PRS_CH4 #1 PRS_CH5 #0 PRS_CH6 #12 ACMP0_O #18 ACMP1_O #18		
20	PD11	BUSCY BUSDX	TIM0_CC0 #19 TIM0_CC1 #18 TIM0_CC2 #17 TIM0_CDTI0 #16 TIM0_CDTI1 #15 TIM0_CDTI2 #14 TIM1_CC0 #19 TIM1_CC1 #18 TIM1_CC2 #17 TIM1_CC3 #16 LE- TIM0_OUT0 #19 LETIM0_OUT1 #18 PCNT0_S0IN #19 PCNT0_S1IN #18	US0_TX #19 US0_RX #18 US0_CLK #17 US0_CS #16 US0_CTS #15 US0_RTS #14 US1_TX #19 US1_RX #18 US1_CLK #17 US1_CS #16 US1_CTS #15 US1_RTS #14 LEU0_TX #19 LEU0_RX #18 I2C0_SDA #19 I2C0_SCL #18	FRC_DCLK #19 FRC_DOUT #18 FRC_DFRAME #17 MODEM_DCLK #19 MODEM_DIN #18 MODEM_DOUT #17 MODEM_ANT0 #16 MODEM_ANT1 #15	PRS_CH3 #10 PRS_CH4 #2 PRS_CH5 #1 PRS_CH6 #13 ACMP0_O #19 ACMP1_O #19		
21	PD12	BUSDY BUSCX	TIM0_CC0 #20 TIM0_CC1 #19 TIM0_CC2 #18 TIM0_CDTI0 #17 TIM0_CDTI1 #16 TIM0_CDTI2 #15 TIM1_CC0 #20 TIM1_CC1 #19 TIM1_CC2 #18 TIM1_CC3 #17 LE- TIM0_OUT0 #20 LETIM0_OUT1 #19 PCNT0_S0IN #20 PCNT0_S1IN #19	US0_TX #20 US0_RX #19 US0_CLK #18 US0_CS #17 US0_CTS #16 US0_RTS #15 US1_TX #20 US1_RX #19 US1_CLK #18 US1_CS #17 US1_CTS #16 US1_RTS #15 LEU0_TX #20 LEU0_RX #19 I2C0_SDA #20 I2C0_SCL #19	FRC_DCLK #20 FRC_DOUT #19 FRC_DFRAME #18 MODEM_DCLK #20 MODEM_DIN #19 MODEM_DOUT #18 MODEM_ANT0 #17 MODEM_ANT1 #16	PRS_CH3 #11 PRS_CH4 #3 PRS_CH5 #2 PRS_CH6 #14 ACMP0_O #20 ACMP1_O #20		

QI	QFN48 Pin# and Pin Alternate Functionality / Description Name							
Pin #	Pin Name	Analog	Timers	Communication	Radio	Other		
22	PD13	BUSCY BUSDX	TIM0_CC0 #21 TIM0_CC1 #20 TIM0_CC2 #19 TIM0_CDTI0 #18 TIM0_CDTI1 #17 TIM0_CDTI2 #16 TIM1_CC0 #21 TIM1_CC1 #20 TIM1_CC2 #19 TIM1_CC3 #18 LE- TIM0_OUT0 #21 LETIM0_OUT1 #20 PCNT0_S0IN #21 PCNT0_S1IN #20	US0_TX #21 US0_RX #20 US0_CLK #19 US0_CS #18 US0_CTS #17 US0_RTS #16 US1_TX #21 US1_RX #20 US1_CLK #19 US1_CLK #19 US1_CTS #17 US1_RTS #16 LEU0_TX #21 LEU0_RX #20 I2C0_SDA #21 I2C0_SCL #20	FRC_DCLK #21 FRC_DOUT #20 FRC_DFRAME #19 MODEM_DCLK #21 MODEM_DIN #20 MODEM_DOUT #19 MODEM_ANT0 #18 MODEM_ANT1 #17	PRS_CH3 #12 PRS_CH4 #4 PRS_CH5 #3 PRS_CH6 #15 ACMP0_O #21 ACMP1_O #21		
23	PD14	BUSDY BUSCX	TIM0_CC0 #22 TIM0_CC1 #21 TIM0_CC2 #20 TIM0_CDTI0 #19 TIM0_CDTI1 #18 TIM0_CDTI2 #17 TIM1_CC0 #22 TIM1_CC1 #21 TIM1_CC2 #20 TIM1_CC3 #19 LE- TIM0_OUT0 #22 LETIM0_OUT1 #21 PCNT0_S0IN #22 PCNT0_S1IN #21	US0_TX #22 US0_RX #21 US0_CLK #20 US0_CS #19 US0_CTS #18 US0_RTS #17 US1_TX #22 US1_RX #21 US1_CLK #20 US1_CS #19 US1_CTS #18 US1_RTS #17 LEU0_TX #22 LEU0_RX #21 I2C0_SDA #22 I2C0_SCL #21	FRC_DCLK #22 FRC_DOUT #21 FRC_DFRAME #20 MODEM_DCLK #22 MODEM_DIN #21 MODEM_DOUT #20 MODEM_ANT0 #19 MODEM_ANT1 #18	CMU_CLK0 #5 PRS_CH3 #13 PRS_CH4 #5 PRS_CH5 #4 PRS_CH6 #16 ACMP0_O #22 ACMP1_O #22 GPIO_EM4WU4		
24	PD15	BUSCY BUSDX	TIM0_CC0 #23 TIM0_CC1 #22 TIM0_CC2 #21 TIM0_CDTI0 #20 TIM0_CDTI1 #19 TIM0_CDTI2 #18 TIM1_CC0 #23 TIM1_CC1 #22 TIM1_CC2 #21 TIM1_CC3 #20 LE- TIM0_OUT0 #23 LETIM0_OUT1 #22 PCNT0_S0IN #23 PCNT0_S1IN #22	US0_TX #23 US0_RX #22 US0_CLK #21 US0_CS #20 US0_CTS #19 US0_RTS #18 US1_TX #23 US1_RX #22 US1_CLK #21 US1_CS #20 US1_CTS #19 US1_RTS #18 LEU0_TX #23 LEU0_RX #22 I2C0_SDA #23 I2C0_SCL #22	FRC_DCLK #23 FRC_DOUT #22 FRC_DFRAME #21 MODEM_DCLK #23 MODEM_DIN #22 MODEM_DOUT #21 MODEM_ANT0 #20 MODEM_ANT1 #19	CMU_CLK1 #5 PRS_CH3 #14 PRS_CH4 #6 PRS_CH5 #5 PRS_CH6 #17 ACMP0_O #23 ACMP1_O #23 DBG_SWO #2		

QI	FN48 Pin# and Name		Pin Altern	ate Functionality / D	escription	
Pin #	Pin Name	Analog	Timers	Communication	Radio	Other
25	PAO	BUSDY BUSCX ADC0_EXTN	TIM0_CC0 #0 TIM0_CC1 #31 TIM0_CC2 #30 TIM0_CDTI0 #29 TIM0_CDTI1 #28 TIM0_CDTI2 #27 TIM1_CC0 #0 TIM1_CC1 #31 TIM1_CC2 #30 TIM1_CC3 #29 LE- TIM0_OUT0 #0 LE- TIM0_OUT0 #0 LE- TIM0_OUT1 #31 PCNT0_S0IN #0 PCNT0_S1IN #31	US0_TX #0 US0_RX #31 US0_CLK #30 US0_CS #29 US0_CTS #28 US0_RTS #27 US1_TX #0 US1_RX #31 US1_CLK #30 US1_CS #29 US1_CTS #28 US1_RTS #27 LEU0_TX #0 LEU0_RX #31 I2C0_SDA #0 I2C0_SCL #31	FRC_DCLK #0 FRC_DOUT #31 FRC_DFRAME #30 MODEM_DCLK #0 MODEM_DIN #31 MODEM_DOUT #30 MODEM_ANT0 #29 MODEM_ANT1 #28	CMU_CLK1 #0 PRS_CH6 #0 PRS_CH7 #10 PRS_CH8 #9 PRS_CH9 #8 ACMP0_O #0 ACMP1_O #0
26	PA1	BUSCY BUSDX ADC0_EXTP	TIM0_CC0 #1 TIM0_CC1 #0 TIM0_CC2 #31 TIM0_CDTI0 #30 TIM0_CDTI1 #29 TIM0_CDTI2 #28 TIM1_CC0 #1 TIM1_CC1 #0 TIM1_CC2 #31 TIM1_CC3 #30 LE- TIM0_OUT0 #1 LE- TIM0_OUT0 #1 LE- TIM0_OUT1 #0 PCNT0_S0IN #1 PCNT0_S1IN #0	US0_TX #1 US0_RX #0 US0_CLK #31 US0_CS #30 US0_CTS #29 US0_RTS #28 US1_TX #1 US1_RX #0 US1_CLK #31 US1_CS #30 US1_CTS #29 US1_RTS #28 LEU0_TX #1 LEU0_RX #0 I2C0_SDA #1 I2C0_SCL #0	FRC_DCLK #1 FRC_DOUT #0 FRC_DFRAME #31 MODEM_DCLK #1 MODEM_DIN #0 MODEM_DOUT #31 MODEM_ANT0 #30 MODEM_ANT1 #29	CMU_CLK0 #0 PRS_CH6 #1 PRS_CH7 #0 PRS_CH8 #10 PRS_CH9 #9 ACMP0_O #1 ACMP1_O #1
27	PA2	BUSDY BUSCX	TIM0_CC0 #2 TIM0_CC1 #1 TIM0_CC2 #0 TIM0_CDTI0 #31 TIM0_CDTI1 #30 TIM0_CDTI2 #29 TIM1_CC0 #2 TIM1_CC1 #1 TIM1_CC2 #0 TIM1_CC3 #31 LE- TIM0_OUT0 #2 LE- TIM0_OUT0 #2 LE- TIM0_OUT1 #1 PCNT0_S0IN #2 PCNT0_S1IN #1	US0_TX #2 US0_RX #1 US0_CLK #0 US0_CS #31 US0_CTS #30 US0_RTS #29 US1_TX #2 US1_RX #1 US1_CLK #0 US1_CS #31 US1_CTS #30 US1_RTS #29 LEU0_TX #2 LEU0_RX #1 I2C0_SDA #2 I2C0_SCL #1	FRC_DCLK #2 FRC_DOUT #1 FRC_DFRAME #0 MODEM_DCLK #2 MODEM_DIN #1 MODEM_DUT #0 MODEM_ANT0 #31 MODEM_ANT1 #30	PRS_CH6 #2 PRS_CH7 #1 PRS_CH8 #0 PRS_CH9 #10 ACMP0_O #2 ACMP1_O #2

QI	FN48 Pin# and Name		Pin Altern	nate Functionality / D	escription	
Pin #	Pin Name	Analog	Timers	Communication	Radio	Other
28	PA3	BUSCY BUSDX	TIM0_CC0 #3 TIM0_CC1 #2 TIM0_CC2 #1 TIM0_CDTI0 #0 TIM0_CDTI1 #31 TIM0_CDTI2 #30 TIM1_CC0 #3 TIM1_CC1 #2 TIM1_CC2 #1 TIM1_CC3 #0 LE- TIM0_OUT0 #3 LE- TIM0_OUT0 #3 LE- TIM0_OUT1 #2 PCNT0_S0IN #3 PCNT0_S1IN #2	US0_TX #3 US0_RX #2 US0_CLK #1 US0_CS #0 US0_CTS #31 US0_RTS #30 US1_TX #3 US1_RX #2 US1_CLK #1 US1_CS #0 US1_CTS #31 US1_RTS #30 LEU0_TX #3 LEU0_RX #2 I2C0_SDA #3 I2C0_SCL #2	FRC_DCLK #3 FRC_DOUT #2 FRC_DFRAME #1 MODEM_DCLK #3 MODEM_DIN #2 MODEM_DOUT #1 MODEM_ANT0 #0 MODEM_ANT1 #31	PRS_CH6 #3 PRS_CH7 #2 PRS_CH8 #1 PRS_CH9 #0 ACMP0_O #3 ACMP1_O #3 GPIO_EM4WU8
29	PA4	BUSDY BUSCX	TIM0_CC0 #4 TIM0_CC1 #3 TIM0_CC2 #2 TIM0_CDTI0 #1 TIM0_CDTI1 #0 TIM0_CDTI2 #31 TIM1_CC0 #4 TIM1_CC1 #3 TIM1_CC2 #2 TIM1_CC3 #1 LE- TIM0_OUT0 #4 LE- TIM0_OUT0 #4 LE- TIM0_OUT1 #3 PCNT0_S0IN #4 PCNT0_S1IN #3	US0_TX #4 US0_RX #3 US0_CLK #2 US0_CS #1 US0_CTS #0 US0_RTS #31 US1_TX #4 US1_RX #3 US1_CLK #2 US1_CS #1 US1_CTS #0 US1_RTS #31 LEU0_TX #4 LEU0_RX #3 I2C0_SDA #4 I2C0_SCL #3	FRC_DCLK #4 FRC_DOUT #3 FRC_DFRAME #2 MODEM_DCLK #4 MODEM_DIN #3 MODEM_DOUT #2 MODEM_ANT0 #1 MODEM_ANT1 #0	PRS_CH6 #4 PRS_CH7 #3 PRS_CH8 #2 PRS_CH9 #1 ACMP0_O #4 ACMP1_O #4
30	PA5	BUSCY BUSDX	TIM0_CC0 #5 TIM0_CC1 #4 TIM0_CC2 #3 TIM0_CDTI0 #2 TIM0_CDTI1 #1 TIM0_CDTI2 #0 TIM1_CC0 #5 TIM1_CC1 #4 TIM1_CC2 #3 TIM1_CC3 #2 LE- TIM0_OUT0 #5 LE- TIM0_OUT0 #5 LE- TIM0_OUT1 #4 PCNT0_S0IN #5 PCNT0_S1IN #4	US0_TX #5 US0_RX #4 US0_CLK #3 US0_CS #2 US0_CTS #1 US0_RTS #0 US1_TX #5 US1_RX #4 US1_CLK #3 US1_CS #2 US1_CTS #1 US1_RTS #0 LEU0_TX #5 LEU0_RX #4 I2C0_SDA #5 I2C0_SCL #4	FRC_DCLK #5 FRC_DOUT #4 FRC_DFRAME #3 MODEM_DCLK #5 MODEM_DIN #4 MODEM_DOUT #3 MODEM_ANT0 #2 MODEM_ANT1 #1	PRS_CH6 #5 PRS_CH7 #4 PRS_CH8 #3 PRS_CH9 #2 ACMP0_O #5 ACMP1_O #5

QF	FN48 Pin# and Name		Pin Altern	nate Functionality / Do	escription	
Pin #	Pin Name	Analog	Timers	Communication	Radio	Other
31	PB11	BUSCY BUSDX	TIM0_CC0 #6 TIM0_CC1 #5 TIM0_CC2 #4 TIM0_CDTI0 #3 TIM0_CDTI1 #2 TIM0_CDTI2 #1 TIM1_CC0 #6 TIM1_CC1 #5 TIM1_CC2 #4 TIM1_CC3 #3 LE- TIM0_OUT0 #6 LE- TIM0_OUT1 #5 PCNT0_S0IN #6 PCNT0_S1IN #5	US0_TX #6 US0_RX #5 US0_CLK #4 US0_CS #3 US0_CTS #2 US0_RTS #1 US1_TX #6 US1_RX #5 US1_CLK #4 US1_CS #3 US1_CTS #2 US1_RTS #1 LEU0_TX #6 LEU0_RX #5 I2C0_SDA #6 I2C0_SCL #5	FRC_DCLK #6 FRC_DOUT #5 FRC_DFRAME #4 MODEM_DCLK #6 MODEM_DIN #5 MODEM_DOUT #4 MODEM_ANT0 #3 MODEM_ANT1 #2	PRS_CH6 #6 PRS_CH7 #5 PRS_CH8 #4 PRS_CH9 #3 ACMP0_O #6 ACMP1_O #6
32	PB12	BUSDY BUSCX	TIM0_CC0 #7 TIM0_CC1 #6 TIM0_CC2 #5 TIM0_CDTI0 #4 TIM0_CDTI1 #3 TIM0_CDTI2 #2 TIM1_CC0 #7 TIM1_CC1 #6 TIM1_CC2 #5 TIM1_CC3 #4 LE- TIM0_OUT0 #7 LE- TIM0_OUT0 #7 LE- TIM0_OUT1 #6 PCNT0_S0IN #7 PCNT0_S1IN #6	US0_TX #7 US0_RX #6 US0_CLK #5 US0_CS #4 US0_CTS #3 US0_RTS #2 US1_TX #7 US1_RX #6 US1_CLK #5 US1_CLK #5 US1_CS #4 US1_CTS #3 US1_RTS #2 LEU0_TX #7 LEU0_RX #6 I2C0_SDA #7 I2C0_SCL #6	FRC_DCLK #7 FRC_DOUT #6 FRC_DFRAME #5 MODEM_DCLK #7 MODEM_DIN #6 MODEM_DOUT #5 MODEM_ANT0 #4 MODEM_ANT1 #3	PRS_CH6 #7 PRS_CH7 #6 PRS_CH8 #5 PRS_CH9 #4 ACMP0_O #7 ACMP1_O #7
33	PB13	BUSCY BUSDX	TIM0_CC0 #8 TIM0_CC1 #7 TIM0_CC2 #6 TIM0_CDTI0 #5 TIM0_CDTI1 #4 TIM0_CDTI2 #3 TIM1_CC0 #8 TIM1_CC1 #7 TIM1_CC2 #6 TIM1_CC3 #5 LE- TIM0_OUT0 #8 LE- TIM0_OUT0 #8 LE- TIM0_OUT1 #7 PCNT0_S0IN #8 PCNT0_S1IN #7	US0_TX #8 US0_RX #7 US0_CLK #6 US0_CS #5 US0_CTS #4 US0_RTS #3 US1_TX #8 US1_RX #7 US1_CLK #6 US1_CS #5 US1_CTS #4 US1_RTS #3 LEU0_TX #8 LEU0_TX #8 LEU0_RX #7 I2C0_SDA #8 I2C0_SCL #7	FRC_DCLK #8 FRC_DOUT #7 FRC_DFRAME #6 MODEM_DCLK #8 MODEM_DIN #7 MODEM_DOUT #6 MODEM_ANT0 #5 MODEM_ANT1 #4	PRS_CH6 #8 PRS_CH7 #7 PRS_CH8 #6 PRS_CH9 #5 ACMP0_O #8 ACMP1_O #8 DBG_SWO #1 GPIO_EM4WU9
34	AVDD	Analog power supply.	1	1	1	

QF	N48 Pin# and Name	Pin Alternate Functionality / Description								
Pin #	Pin Name	Analog	Timers	Communication	Radio	Other				
35	PB14	BUSDY BUSCX LFXTAL_N	TIM0_CC0 #9 TIM0_CC1 #8 TIM0_CC2 #7 TIM0_CDTI0 #6 TIM0_CDTI1 #5 TIM0_CDTI2 #4 TIM1_CC0 #9 TIM1_CC1 #8 TIM1_CC2 #7 TIM1_CC3 #6 LE- TIM0_OUT0 #9 LE- TIM0_OUT0 #9 LE- TIM0_OUT1 #8 PCNT0_S0IN #9 PCNT0_S1IN #8	US0_TX #9 US0_RX #8 US0_CLK #7 US0_CS #6 US0_CTS #5 US0_RTS #4 US1_TX #9 US1_RX #8 US1_CLK #7 US1_CS #6 US1_CTS #5 US1_RTS #4 LEU0_TX #9 LEU0_RX #8 I2C0_SDA #9 I2C0_SCL #8	FRC_DCLK #9 FRC_DOUT #8 FRC_DFRAME #7 MODEM_DCLK #9 MODEM_DIN #8 MODEM_DUT #7 MODEM_ANT0 #6 MODEM_ANT1 #5	CMU_CLK1 #1 PRS_CH6 #9 PRS_CH7 #8 PRS_CH8 #7 PRS_CH9 #6 ACMP0_O #9 ACMP1_O #9				
36	PB15	BUSCY BUSDX LFXTAL_P	TIM0_CC0 #10 TIM0_CC1 #9 TIM0_CC2 #8 TIM0_CDTI0 #7 TIM0_CDTI1 #6 TIM0_CDTI2 #5 TIM1_CC0 #10 TIM1_CC1 #9 TIM1_CC2 #8 TIM1_CC3 #7 LE- TIM0_OUT0 #10 LETIM0_OUT1 #9 PCNT0_S0IN #10 PCNT0_S1IN #9	US0_TX #10 US0_RX #9 US0_CLK #8 US0_CS #7 US0_CTS #6 US0_RTS #5 US1_TX #10 US1_RX #9 US1_CLK #8 US1_CS #7 US1_CTS #6 US1_RTS #5 LEU0_TX #10 LEU0_RX #9 I2C0_SDA #10 I2C0_SCL #9	FRC_DCLK #10 FRC_DOUT #9 FRC_DFRAME #8 MODEM_DCLK #10 MODEM_DIN #9 MODEM_DOUT #8 MODEM_ANT0 #7 MODEM_ANT1 #6	CMU_CLK0 #1 PRS_CH6 #10 PRS_CH7 #9 PRS_CH8 #8 PRS_CH9 #7 ACMP0_O #10 ACMP1_O #10				
37	VREGVSS	Voltage regulator VSS	6							
38	VREGSW	DCDC regulator swite	ching node							
39	VREGVDD	Voltage regulator VDI	D input							
40	DVDD	Digital power supply.								
41	DECOUPLE	Decouple output for o pin.	n-chip voltage regulato	or. An external capacit	ance of size C _{DECOUPLE}	is required at this				
	IOVDD	Digital IO power supply.								

QI	FN48 Pin# and Name		Pin Altern	ate Functionality / D	escription	
Pin #	Pin Name	Analog	Timers	Communication	Radio	Other
43	PC6	BUSBY BUSAX	TIM0_CC0 #11 TIM0_CC1 #10 TIM0_CC2 #9 TIM0_CDTI0 #8 TIM0_CDTI1 #7 TIM0_CDT12 #6 TIM1_CC0 #11 TIM1_CC1 #10 TIM1_CC2 #9 TIM1_CC3 #8 LE- TIM0_OUT0 #11 LE- TIM0_OUT0 #11 LE- TIM0_OUT1 #10 PCNT0_S0IN #11 PCNT0_S1IN #10	US0_TX #11 US0_RX #10 US0_CLK #9 US0_CS #8 US0_CTS #7 US0_RTS #6 US1_TX #11 US1_RX #10 US1_CLK #9 US1_CS #8 US1_CTS #7 US1_RTS #6 LEU0_TX #11 LEU0_RX #10 I2C0_SDA #11 I2C0_SCL #10	FRC_DCLK #11 FRC_DOUT #10 FRC_DFRAME #9 MODEM_DCLK #11 MODEM_DIN #10 MODEM_DOUT #9 MODEM_ANT0 #8 MODEM_ANT1 #7	CMU_CLK0 #2 PRS_CH0 #8 PRS_CH9 #11 PRS_CH10 #0 PRS_CH11 #5 ACMP0_O #11 ACMP1_O #11
44	PC7	BUSAY BUSBX	TIM0_CC0 #12 TIM0_CC1 #11 TIM0_CC2 #10 TIM0_CDTI0 #9 TIM0_CDT11 #8 TIM0_CDT12 #7 TIM1_CC0 #12 TIM1_CC1 #11 TIM1_CC2 #10 TIM1_CC3 #9 LE- TIM0_OUT0 #12 LETIM0_OUT1 #11 PCNT0_S0IN #12 PCNT0_S1IN #11	US0_TX #12 US0_RX #11 US0_CLK #10 US0_CS #9 US0_CTS #8 US0_RTS #7 US1_TX #12 US1_RX #11 US1_CLK #10 US1_CS #9 US1_CTS #8 US1_RTS #7 LEU0_TX #12 LEU0_RX #11 I2C0_SDA #12 I2C0_SCL #11	FRC_DCLK #12 FRC_DOUT #11 FRC_DFRAME #10 MODEM_DCLK #12 MODEM_DIN #11 MODEM_DOUT #10 MODEM_ANT0 #9 MODEM_ANT1 #8	CMU_CLK1 #2 PRS_CH0 #9 PRS_CH9 #12 PRS_CH10 #1 PRS_CH11 #0 ACMP0_O #12 ACMP1_O #12
45	PC8	BUSBY BUSAX	TIM0_CC0 #13 TIM0_CC1 #12 TIM0_CC2 #11 TIM0_CDTI0 #10 TIM0_CDT11 #9 TIM0_CDT12 #8 TIM1_CC0 #13 TIM1_CC1 #12 TIM1_CC2 #11 TIM1_CC3 #10 LE- TIM0_OUT0 #13 LETIM0_OUT1 #12 PCNT0_S0IN #13 PCNT0_S1IN #12	US0_TX #13 US0_RX #12 US0_CLK #11 US0_CS #10 US0_CTS #9 US0_RTS #8 US1_TX #13 US1_RX #12 US1_CLK #11 US1_CS #10 US1_CTS #9 US1_RTS #8 LEU0_TX #13 LEU0_RX #12 I2C0_SDA #13 I2C0_SCL #12	FRC_DCLK #13 FRC_DOUT #12 FRC_DFRAME #11 MODEM_DCLK #13 MODEM_DIN #12 MODEM_DOUT #11 MODEM_ANT0 #10 MODEM_ANT1 #9	PRS_CH0 #10 PRS_CH9 #13 PRS_CH10 #2 PRS_CH11 #1 ACMP0_O #13 ACMP1_O #13

QI	FN48 Pin# and Name		Pin Altern	ate Functionality / D	escription	
Pin #	Pin Name	Analog	Timers	Communication	Radio	Other
46	PC9	BUSAY BUSBX	TIM0_CC0 #14 TIM0_CC1 #13 TIM0_CC2 #12 TIM0_CDTI0 #11 TIM0_CDTI1 #10 TIM0_CDTI2 #9 TIM1_CC0 #14 TIM1_CC1 #13 TIM1_CC2 #12 TIM1_CC3 #11 LE- TIM0_OUT0 #14 LETIM0_OUT1 #13 PCNT0_S0IN #14 PCNT0_S1IN #13	US0_TX #14 US0_RX #13 US0_CLK #12 US0_CS #11 US0_CTS #10 US0_RTS #9 US1_TX #14 US1_RX #13 US1_CLK #12 US1_CS #11 US1_CTS #10 US1_RTS #9 LEU0_TX #14 LEU0_RX #13 I2C0_SDA #14 I2C0_SCL #13	FRC_DCLK #14 FRC_DOUT #13 FRC_DFRAME #12 MODEM_DCLK #14 MODEM_DIN #13 MODEM_DOUT #12 MODEM_ANT0 #11 MODEM_ANT1 #10	PRS_CH0 #11 PRS_CH9 #14 PRS_CH10 #3 PRS_CH11 #2 ACMP0_O #14 ACMP1_O #14
47	PC10	BUSBY BUSAX	TIM0_CC0 #15 TIM0_CC1 #14 TIM0_CC2 #13 TIM0_CDTI0 #12 TIM0_CDTI1 #11 TIM0_CDTI2 #10 TIM1_CC0 #15 TIM1_CC1 #14 TIM1_CC2 #13 TIM1_CC3 #12 LE- TIM0_OUT0 #15 LETIM0_OUT1 #14 PCNT0_S0IN #15 PCNT0_S1IN #14	US0_TX #15 US0_RX #14 US0_CLK #13 US0_CS #12 US0_CTS #11 US0_RTS #10 US1_TX #15 US1_RX #14 US1_CLK #13 US1_CS #12 US1_CTS #11 US1_RTS #10 LEU0_TX #15 LEU0_RX #14 I2C0_SDA #15 I2C0_SCL #14	FRC_DCLK #15 FRC_DOUT #14 FRC_DFRAME #13 MODEM_DCLK #15 MODEM_DIN #14 MODEM_DOUT #13 MODEM_ANT0 #12 MODEM_ANT1 #11	CMU_CLK1 #3 PRS_CH0 #12 PRS_CH9 #15 PRS_CH10 #4 PRS_CH11 #3 ACMP0_O #15 ACMP1_O #15 GPIO_EM4WU12
48	PC11	BUSAY BUSBX	TIM0_CC0 #16 TIM0_CC1 #15 TIM0_CC2 #14 TIM0_CDTI0 #13 TIM0_CDTI1 #12 TIM0_CDTI2 #11 TIM1_CC0 #16 TIM1_CC1 #15 TIM1_CC2 #14 TIM1_CC3 #13 LE- TIM0_OUT0 #16 LETIM0_OUT1 #15 PCNT0_S0IN #16 PCNT0_S1IN #15	US0_TX #16 US0_RX #15 US0_CLK #14 US0_CS #13 US0_CTS #12 US0_RTS #11 US1_TX #16 US1_RX #15 US1_CLK #14 US1_CS #13 US1_CTS #12 US1_RTS #11 LEU0_TX #16 LEU0_RX #15 I2C0_SDA #16 I2C0_SCL #15	FRC_DCLK #16 FRC_DOUT #15 FRC_DFRAME #14 MODEM_DCLK #16 MODEM_DIN #15 MODEM_DOUT #14 MODEM_ANT0 #13 MODEM_ANT1 #12	CMU_CLK0 #3 PRS_CH0 #13 PRS_CH9 #16 PRS_CH10 #5 PRS_CH11 #4 ACMP0_O #16 ACMP1_O #16 DBG_SWO #3

6.2 Alternate Functionality Pinout

A wide selection of alternate functionality is available for multiplexing to various pins. The following table shows the name of the alternate functionality in the first column, followed by columns showing the possible LOCATION bitfield settings.

Note: Some functionality, such as analog interfaces, do not have alternate settings or a LOCATION bitfield. In these cases, the pinout is shown in the column corresponding to LOCATION 0.

Alternate				LOCA	TION				
Functionality	0 - 3	4 - 7	8 - 11	12 - 15	16 - 19	20 - 23	24 - 27	28 - 31	Description
ACMP0_O	0: PA0 1: PA1 2: PA2 3: PA3	4: PA4 5: PA5 6: PB11 7: PB12	8: PB13 9: PB14 10: PB15 11: PC6	12: PC7 13: PC8 14: PC9 15: PC10	16: PC11 18: PD10 19: PD11	20: PD12 21: PD13 22: PD14 23: PD15	24: PF0 25: PF1 26: PF2 27: PF3	28: PF4 29: PF5 30: PF6 31: PF7	Analog comparator ACMP0, digital out- put.
ACMP1_O	0: PA0 1: PA1 2: PA2 3: PA3	4: PA4 5: PA5 6: PB11 7: PB12	8: PB13 9: PB14 10: PB15 11: PC6	12: PC7 13: PC8 14: PC9 15: PC10	16: PC11 18: PD10 19: PD11	20: PD12 21: PD13 22: PD14 23: PD15	24: PF0 25: PF1 26: PF2 27: PF3	28: PF4 29: PF5 30: PF6 31: PF7	Analog comparator ACMP1, digital out- put.
ADC0_EXTN	0: PA0								Analog to digital converter ADC0 ex- ternal reference in- put negative pin
ADC0_EXTP	0: PA1								Analog to digital converter ADC0 ex- ternal reference in- put positive pin
BOOT_RX	0: PF1								Bootloader RX
BOOT_TX	0: PF0							4	Bootloader TX
CMU_CLK0	0: PA1 1: PB15 2: PC6 3: PC11	5: PD14 6: PF2 7: PF7							Clock Management Unit, clock output number 0.
CMU_CLK1	0: PA0 1: PB14 2: PC7 3: PC10	4: PD10 5: PD15 6: PF3 7: PF6							Clock Management Unit, clock output number 1.
DBG_SWCLKTCK	0: PF0								Debug-interface Serial Wire clock input and JTAG Test Clock. Note that this func- tion is enabled to pin out of reset, and has a built-in pull down.

Table 6.2. Alternate functionality overview

Alternate				LOCA	ATION				
Functionality	0 - 3	4 - 7	8 - 11	12 - 15	16 - 19	20 - 23	24 - 27	28 - 31	Description
	0: PF1								Debug-interface Serial Wire data in- put / output and JTAG Test Mode Select.
DBG_SWDIOTMS									Note that this func- tion is enabled to pin out of reset, and has a built-in pull up.
	0: PF2								Debug-interface Serial Wire viewer Output.
DBG_SWO	0: PF2 1: PB13 2: PD15 3: PC11								Note that this func- tion is not enabled after reset, and must be enabled by software to be used.
									Debug-interface JTAG Test Data In.
DBG_TDI	0: PF3								Note that this func- tion is enabled to pin out of reset, and has a built-in pull up.
DBG_TDO	0: PF2								Debug-interface JTAG Test Data Out.
									Note that this func- tion is enabled to pin out of reset.
FRC_DCLK	0: PA0 1: PA1 2: PA2 3: PA3	4: PA4 5: PA5 6: PB11 7: PB12	8: PB13 9: PB14 10: PB15 11: PC6	12: PC7 13: PC8 14: PC9 15: PC10	16: PC11 18: PD10 19: PD11	20: PD12 21: PD13 22: PD14 23: PD15	24: PF0 25: PF1 26: PF2 27: PF3	28: PF4 29: PF5 30: PF6 31: PF7	Frame Controller, Data Sniffer Clock.
FRC_DFRAME	0: PA2 1: PA3 2: PA4 3: PA5	4: PB11 5: PB12 6: PB13 7: PB14	8: PB15 9: PC6 10: PC7 11: PC8	12: PC9 13: PC10 14: PC11	16: PD10 17: PD11 18: PD12 19: PD13	20: PD14 21: PD15 22: PF0 23: PF1	24: PF2 25: PF3 26: PF4 27: PF5	28: PF6 29: PF7 30: PA0 31: PA1	Frame Controller, Data Sniffer Frame active
FRC_DOUT	0: PA1 1: PA2 2: PA3 3: PA4	4: PA5 5: PB11 6: PB12 7: PB13	8: PB14 9: PB15 10: PC6 11: PC7	12: PC8 13: PC9 14: PC10 15: PC11	17: PD10 18: PD11 19: PD12	20: PD13 21: PD14 22: PD15 23: PF0	24: PF1 25: PF2 26: PF3 27: PF4	28: PF5 29: PF6 30: PF7 31: PA0	Frame Controller, Data Sniffer Out- put.
GPIO_EM4WU0	0: PF2								Pin can be used to wake the system up from EM4
GPIO_EM4WU1	0: PF7								Pin can be used to wake the system up from EM4

Alternate				LOCA	ATION				
Functionality	0 - 3	4 - 7	8 - 11	12 - 15	16 - 19	20 - 23	24 - 27	28 - 31	Description
GPIO_EM4WU4	0: PD14								Pin can be used to wake the system up from EM4
GPIO_EM4WU8	0: PA3								Pin can be used to wake the system up from EM4
GPIO_EM4WU9	0: PB13								Pin can be used to wake the system up from EM4
GPIO_EM4WU12	0: PC10								Pin can be used to wake the system up from EM4
I2C0_SCL	0: PA1 1: PA2 2: PA3 3: PA4	4: PA5 5: PB11 6: PB12 7: PB13	8: PB14 9: PB15 10: PC6 11: PC7	12: PC8 13: PC9 14: PC10 15: PC11	17: PD10 18: PD11 19: PD12	20: PD13 21: PD14 22: PD15 23: PF0	24: PF1 25: PF2 26: PF3 27: PF4	28: PF5 29: PF6 30: PF7 31: PA0	I2C0 Serial Clock Line input / output.
I2C0_SDA	0: PA0 1: PA1 2: PA2 3: PA3	4: PA4 5: PA5 6: PB11 7: PB12	8: PB13 9: PB14 10: PB15 11: PC6	12: PC7 13: PC8 14: PC9 15: PC10	16: PC11 18: PD10 19: PD11	20: PD12 21: PD13 22: PD14 23: PD15	24: PF0 25: PF1 26: PF2 27: PF3	28: PF4 29: PF5 30: PF6 31: PF7	I2C0 Serial Data in- put / output.
LETIM0_OUT0	0: PA0 1: PA1 2: PA2 3: PA3	4: PA4 5: PA5 6: PB11 7: PB12	8: PB13 9: PB14 10: PB15 11: PC6	12: PC7 13: PC8 14: PC9 15: PC10	16: PC11 18: PD10 19: PD11	20: PD12 21: PD13 22: PD14 23: PD15	24: PF0 25: PF1 26: PF2 27: PF3	28: PF4 29: PF5 30: PF6 31: PF7	Low Energy Timer LETIM0, output channel 0.
LETIM0_OUT1	0: PA1 1: PA2 2: PA3 3: PA4	4: PA5 5: PB11 6: PB12 7: PB13	8: PB14 9: PB15 10: PC6 11: PC7	12: PC8 13: PC9 14: PC10 15: PC11	17: PD10 18: PD11 19: PD12	20: PD13 21: PD14 22: PD15 23: PF0	24: PF1 25: PF2 26: PF3 27: PF4	28: PF5 29: PF6 30: PF7 31: PA0	Low Energy Timer LETIM0, output channel 1.
LEU0_RX	0: PA1 1: PA2 2: PA3 3: PA4	4: PA5 5: PB11 6: PB12 7: PB13	8: PB14 9: PB15 10: PC6 11: PC7	12: PC8 13: PC9 14: PC10 15: PC11	17: PD10 18: PD11 19: PD12	20: PD13 21: PD14 22: PD15 23: PF0	24: PF1 25: PF2 26: PF3 27: PF4	28: PF5 29: PF6 30: PF7 31: PA0	LEUART0 Receive input.
LEU0_TX	0: PA0 1: PA1 2: PA2 3: PA3	4: PA4 5: PA5 6: PB11 7: PB12	8: PB13 9: PB14 10: PB15 11: PC6	12: PC7 13: PC8 14: PC9 15: PC10	16: PC11 18: PD10 19: PD11	20: PD12 21: PD13 22: PD14 23: PD15	24: PF0 25: PF1 26: PF2 27: PF3	28: PF4 29: PF5 30: PF6 31: PF7	LEUARTO Transmit output. Also used as receive input in half duplex commu- nication.
LFXTAL_N	0: PB14								Low Frequency Crystal (typically 32.768 kHz) nega- tive pin. Also used as an optional ex- ternal clock input pin.
LFXTAL_P	0: PB15								Low Frequency Crystal (typically 32.768 kHz) posi- tive pin.

Alternate				LOC	ATION				
Functionality	0 - 3	4 - 7	8 - 11	12 - 15	16 - 19	20 - 23	24 - 27	28 - 31	Description
MODEM_ANT0	0: PA3 1: PA4 2: PA5 3: PB11	4: PB12 5: PB13 6: PB14 7: PB15	8: PC6 9: PC7 10: PC8 11: PC9	12: PC10 13: PC11 15: PD10	16: PD11 17: PD12 18: PD13 19: PD14	20: PD15 21: PF0 22: PF1 23: PF2	24: PF3 25: PF4 26: PF5 27: PF6	28: PF7 29: PA0 30: PA1 31: PA2	MODEM antenna control output 0, used for antenna diversity.
MODEM_ANT1	0: PA4 1: PA5 2: PB11 3: PB12	4: PB13 5: PB14 6: PB15 7: PC6	8: PC7 9: PC8 10: PC9 11: PC10	12: PC11 14: PD10 15: PD11	16: PD12 17: PD13 18: PD14 19: PD15	20: PF0 21: PF1 22: PF2 23: PF3	24: PF4 25: PF5 26: PF6 27: PF7	28: PA0 29: PA1 30: PA2 31: PA3	MODEM antenna control output 1, used for antenna diversity.
MODEM_DCLK	0: PA0 1: PA1 2: PA2 3: PA3	4: PA4 5: PA5 6: PB11 7: PB12	8: PB13 9: PB14 10: PB15 11: PC6	12: PC7 13: PC8 14: PC9 15: PC10	16: PC11 18: PD10 19: PD11	20: PD12 21: PD13 22: PD14 23: PD15	24: PF0 25: PF1 26: PF2 27: PF3	28: PF4 29: PF5 30: PF6 31: PF7	MODEM data clock out.
MODEM_DIN	0: PA1 1: PA2 2: PA3 3: PA4	4: PA5 5: PB11 6: PB12 7: PB13	8: PB14 9: PB15 10: PC6 11: PC7	12: PC8 13: PC9 14: PC10 15: PC11	17: PD10 18: PD11 19: PD12	20: PD13 21: PD14 22: PD15 23: PF0	24: PF1 25: PF2 26: PF3 27: PF4	28: PF5 29: PF6 30: PF7 31: PA0	MODEM data in.
MODEM_DOUT	0: PA2 1: PA3 2: PA4 3: PA5	4: PB11 5: PB12 6: PB13 7: PB14	8: PB15 9: PC6 10: PC7 11: PC8	12: PC9 13: PC10 14: PC11	16: PD10 17: PD11 18: PD12 19: PD13	20: PD14 21: PD15 22: PF0 23: PF1	24: PF2 25: PF3 26: PF4 27: PF5	28: PF6 29: PF7 30: PA0 31: PA1	MODEM data out.
PCNT0_S0IN	0: PA0 1: PA1 2: PA2 3: PA3	4: PA4 5: PA5 6: PB11 7: PB12	8: PB13 9: PB14 10: PB15 11: PC6	12: PC7 13: PC8 14: PC9 15: PC10	16: PC11 18: PD10 19: PD11	20: PD12 21: PD13 22: PD14 23: PD15	24: PF0 25: PF1 26: PF2 27: PF3	28: PF4 29: PF5 30: PF6 31: PF7	Pulse Counter PCNT0 input num- ber 0.
PCNT0_S1IN	0: PA1 1: PA2 2: PA3 3: PA4	4: PA5 5: PB11 6: PB12 7: PB13	8: PB14 9: PB15 10: PC6 11: PC7	12: PC8 13: PC9 14: PC10 15: PC11	17: PD10 18: PD11 19: PD12	20: PD13 21: PD14 22: PD15 23: PF0	24: PF1 25: PF2 26: PF3 27: PF4	28: PF5 29: PF6 30: PF7 31: PA0	Pulse Counter PCNT0 input num- ber 1.
PRS_CH0	0: PF0 1: PF1 2: PF2 3: PF3	4: PF4 5: PF5 6: PF6 7: PF7	8: PC6 9: PC7 10: PC8 11: PC9	12: PC10 13: PC11					Peripheral Reflex System PRS, chan- nel 0.
PRS_CH1	0: PF1 1: PF2 2: PF3 3: PF4	4: PF5 5: PF6 6: PF7 7: PF0						6	Peripheral Reflex System PRS, chan- nel 1.
PRS_CH2	0: PF2 1: PF3 2: PF4 3: PF5	4: PF6 5: PF7 6: PF0 7: PF1							Peripheral Reflex System PRS, chan- nel 2.
PRS_CH3	0: PF3 1: PF4 2: PF5 3: PF6	4: PF7 5: PF0 6: PF1 7: PF2	9: PD10 10: PD11 11: PD12	12: PD13 13: PD14 14: PD15					Peripheral Reflex System PRS, chan- nel 3.
PRS_CH4	1: PD10 2: PD11 3: PD12	4: PD13 5: PD14 6: PD15							Peripheral Reflex System PRS, chan- nel 4.
PRS_CH5	0: PD10 1: PD11 2: PD12 3: PD13	4: PD14 5: PD15							Peripheral Reflex System PRS, chan- nel 5.

Alternate				LOCA	ATION				
Functionality	0 - 3	4 - 7	8 - 11	12 - 15	16 - 19	20 - 23	24 - 27	28 - 31	Description
PRS_CH6	0: PA0 1: PA1 2: PA2 3: PA3	4: PA4 5: PA5 6: PB11 7: PB12	8: PB13 9: PB14 10: PB15	12: PD10 13: PD11 14: PD12 15: PD13	16: PD14 17: PD15				Peripheral Reflex System PRS, chan- nel 6.
PRS_CH7	0: PA1 1: PA2 2: PA3 3: PA4	4: PA5 5: PB11 6: PB12 7: PB13	8: PB14 9: PB15 10: PA0						Peripheral Reflex System PRS, chan- nel 7.
PRS_CH8	0: PA2 1: PA3 2: PA4 3: PA5	4: PB11 5: PB12 6: PB13 7: PB14	8: PB15 9: PA0 10: PA1						Peripheral Reflex System PRS, chan- nel 8.
PRS_CH9	0: PA3 1: PA4 2: PA5 3: PB11	4: PB12 5: PB13 6: PB14 7: PB15	8: PA0 9: PA1 10: PA2 11: PC6	12: PC7 13: PC8 14: PC9 15: PC10	16: PC11				Peripheral Reflex System PRS, chan- nel 9.
PRS_CH10	0: PC6 1: PC7 2: PC8 3: PC9	4: PC10 5: PC11							Peripheral Reflex System PRS, chan- nel 10.
PRS_CH11	0: PC7 1: PC8 2: PC9 3: PC10	4: PC11 5: PC6							Peripheral Reflex System PRS, chan- nel 11.
ТІМ0_СС0	0: PA0 1: PA1 2: PA2 3: PA3	4: PA4 5: PA5 6: PB11 7: PB12	8: PB13 9: PB14 10: PB15 11: PC6	12: PC7 13: PC8 14: PC9 15: PC10	16: PC11 18: PD10 19: PD11	20: PD12 21: PD13 22: PD14 23: PD15	24: PF0 25: PF1 26: PF2 27: PF3	28: PF4 29: PF5 30: PF6 31: PF7	Timer 0 Capture Compare input / output channel 0.
TIM0_CC1	0: PA1 1: PA2 2: PA3 3: PA4	4: PA5 5: PB11 6: PB12 7: PB13	8: PB14 9: PB15 10: PC6 11: PC7	12: PC8 13: PC9 14: PC10 15: PC11	17: PD10 18: PD11 19: PD12	20: PD13 21: PD14 22: PD15 23: PF0	24: PF1 25: PF2 26: PF3 27: PF4	28: PF5 29: PF6 30: PF7 31: PA0	Timer 0 Capture Compare input / output channel 1.
TIM0_CC2	0: PA2 1: PA3 2: PA4 3: PA5	4: PB11 5: PB12 6: PB13 7: PB14	8: PB15 9: PC6 10: PC7 11: PC8	12: PC9 13: PC10 14: PC11	16: PD10 17: PD11 18: PD12 19: PD13	20: PD14 21: PD15 22: PF0 23: PF1	24: PF2 25: PF3 26: PF4 27: PF5	28: PF6 29: PF7 30: PA0 31: PA1	Timer 0 Capture Compare input / output channel 2.
TIM0_CDTI0	0: PA3 1: PA4 2: PA5 3: PB11	4: PB12 5: PB13 6: PB14 7: PB15	8: PC6 9: PC7 10: PC8 11: PC9	12: PC10 13: PC11 15: PD10	16: PD11 17: PD12 18: PD13 19: PD14	20: PD15 21: PF0 22: PF1 23: PF2	24: PF3 25: PF4 26: PF5 27: PF6	28: PF7 29: PA0 30: PA1 31: PA2	Timer 0 Compli- mentary Deat Time Insertion channel 0.
TIM0_CDTI1	0: PA4 1: PA5 2: PB11 3: PB12	4: PB13 5: PB14 6: PB15 7: PC6	8: PC7 9: PC8 10: PC9 11: PC10	12: PC11 14: PD10 15: PD11	16: PD12 17: PD13 18: PD14 19: PD15	20: PF0 21: PF1 22: PF2 23: PF3	24: PF4 25: PF5 26: PF6 27: PF7	28: PA0 29: PA1 30: PA2 31: PA3	Timer 0 Compli- mentary Deat Time Insertion channel 1.
TIM0_CDTI2	0: PA5 1: PB11 2: PB12 3: PB13	4: PB14 5: PB15 6: PC6 7: PC7	8: PC8 9: PC9 10: PC10 11: PC11	13: PD10 14: PD11 15: PD12	16: PD13 17: PD14 18: PD15 19: PF0	20: PF1 21: PF2 22: PF3 23: PF4	24: PF5 25: PF6 26: PF7 27: PA0	28: PA1 29: PA2 30: PA3 31: PA4	Timer 0 Compli- mentary Deat Time Insertion channel 2.
TIM1_CC0	0: PA0 1: PA1 2: PA2 3: PA3	4: PA4 5: PA5 6: PB11 7: PB12	8: PB13 9: PB14 10: PB15 11: PC6	12: PC7 13: PC8 14: PC9 15: PC10	16: PC11 18: PD10 19: PD11	20: PD12 21: PD13 22: PD14 23: PD15	24: PF0 25: PF1 26: PF2 27: PF3	28: PF4 29: PF5 30: PF6 31: PF7	Timer 1 Capture Compare input / output channel 0.

Alternate				LOC	ATION				
Functionality	0 - 3	4 - 7	8 - 11	12 - 15	16 - 19	20 - 23	24 - 27	28 - 31	Description
TIM1_CC1	0: PA1 1: PA2 2: PA3 3: PA4	4: PA5 5: PB11 6: PB12 7: PB13	8: PB14 9: PB15 10: PC6 11: PC7	12: PC8 13: PC9 14: PC10 15: PC11	17: PD10 18: PD11 19: PD12	20: PD13 21: PD14 22: PD15 23: PF0	24: PF1 25: PF2 26: PF3 27: PF4	28: PF5 29: PF6 30: PF7 31: PA0	Timer 1 Capture Compare input / output channel 1.
TIM1_CC2	0: PA2 1: PA3 2: PA4 3: PA5	4: PB11 5: PB12 6: PB13 7: PB14	8: PB15 9: PC6 10: PC7 11: PC8	12: PC9 13: PC10 14: PC11	16: PD10 17: PD11 18: PD12 19: PD13	20: PD14 21: PD15 22: PF0 23: PF1	24: PF2 25: PF3 26: PF4 27: PF5	28: PF6 29: PF7 30: PA0 31: PA1	Timer 1 Capture Compare input / output channel 2.
TIM1_CC3	0: PA3 1: PA4 2: PA5 3: PB11	4: PB12 5: PB13 6: PB14 7: PB15	8: PC6 9: PC7 10: PC8 11: PC9	12: PC10 13: PC11 15: PD10	16: PD11 17: PD12 18: PD13 19: PD14	20: PD15 21: PF0 22: PF1 23: PF2	24: PF3 25: PF4 26: PF5 27: PF6	28: PF7 29: PA0 30: PA1 31: PA2	Timer 1 Capture Compare input / output channel 3.
US0_CLK	0: PA2 1: PA3 2: PA4 3: PA5	4: PB11 5: PB12 6: PB13 7: PB14	8: PB15 9: PC6 10: PC7 11: PC8	12: PC9 13: PC10 14: PC11	16: PD10 17: PD11 18: PD12 19: PD13	20: PD14 21: PD15 22: PF0 23: PF1	24: PF2 25: PF3 26: PF4 27: PF5	28: PF6 29: PF7 30: PA0 31: PA1	USART0 clock in- put / output.
US0_CS	0: PA3 1: PA4 2: PA5 3: PB11	4: PB12 5: PB13 6: PB14 7: PB15	8: PC6 9: PC7 10: PC8 11: PC9	12: PC10 13: PC11 15: PD10	16: PD11 17: PD12 18: PD13 19: PD14	20: PD15 21: PF0 22: PF1 23: PF2	24: PF3 25: PF4 26: PF5 27: PF6	28: PF7 29: PA0 30: PA1 31: PA2	USART0 chip se- lect input / output.
US0_CTS	0: PA4 1: PA5 2: PB11 3: PB12	4: PB13 5: PB14 6: PB15 7: PC6	8: PC7 9: PC8 10: PC9 11: PC10	12: PC11 14: PD10 15: PD11	16: PD12 17: PD13 18: PD14 19: PD15	20: PF0 21: PF1 22: PF2 23: PF3	24: PF4 25: PF5 26: PF6 27: PF7	28: PA0 29: PA1 30: PA2 31: PA3	USART0 clear to send hardware flow control input.
US0_RTS	0: PA5 1: PB11 2: PB12 3: PB13	4: PB14 5: PB15 6: PC6 7: PC7	8: PC8 9: PC9 10: PC10 11: PC11	13: PD10 14: PD11 15: PD12	16: PD13 17: PD14 18: PD15 19: PF0	20: PF1 21: PF2 22: PF3 23: PF4	24: PF5 25: PF6 26: PF7 27: PA0	28: PA1 29: PA2 30: PA3 31: PA4	USART0 request to send hardware flow control output.
US0_RX	0: PA1 1: PA2 2: PA3 3: PA4	4: PA5 5: PB11 6: PB12 7: PB13	8: PB14 9: PB15 10: PC6 11: PC7	12: PC8 13: PC9 14: PC10 15: PC11	17: PD10 18: PD11 19: PD12	20: PD13 21: PD14 22: PD15 23: PF0	24: PF1 25: PF2 26: PF3 27: PF4	28: PF5 29: PF6 30: PF7 31: PA0	USART0 Asynchro- nous Receive. USART0 Synchro- nous mode Master Input / Slave Out- put (MISO).
US0_TX	0: PA0 1: PA1 2: PA2 3: PA3	4: PA4 5: PA5 6: PB11 7: PB12	8: PB13 9: PB14 10: PB15 11: PC6	12: PC7 13: PC8 14: PC9 15: PC10	16: PC11 18: PD10 19: PD11	20: PD12 21: PD13 22: PD14 23: PD15	24: PF0 25: PF1 26: PF2 27: PF3	28: PF4 29: PF5 30: PF6 31: PF7	USART0 Asynchro- nous Transmit.Also used as receive in- put in half duplex communication. USART0 Synchro- nous mode Master Output / Slave In- put (MOSI).
US1_CLK	0: PA2 1: PA3 2: PA4 3: PA5	4: PB11 5: PB12 6: PB13 7: PB14	8: PB15 9: PC6 10: PC7 11: PC8	12: PC9 13: PC10 14: PC11	16: PD10 17: PD11 18: PD12 19: PD13	20: PD14 21: PD15 22: PF0 23: PF1	24: PF2 25: PF3 26: PF4 27: PF5	28: PF6 29: PF7 30: PA0 31: PA1	USART1 clock in- put / output.
US1_CS	0: PA3 1: PA4 2: PA5 3: PB11	4: PB12 5: PB13 6: PB14 7: PB15	8: PC6 9: PC7 10: PC8 11: PC9	12: PC10 13: PC11 15: PD10	16: PD11 17: PD12 18: PD13 19: PD14	20: PD15 21: PF0 22: PF1 23: PF2	24: PF3 25: PF4 26: PF5 27: PF6	28: PF7 29: PA0 30: PA1 31: PA2	USART1 chip se- lect input / output.

Alternate				LOCA	ATION	_			
Functionality	0 - 3	4 - 7	8 - 11	12 - 15	16 - 19	20 - 23	24 - 27	28 - 31	Description
US1_CTS	0: PA4 1: PA5 2: PB11 3: PB12	4: PB13 5: PB14 6: PB15 7: PC6	8: PC7 9: PC8 10: PC9 11: PC10	12: PC11 14: PD10 15: PD11	16: PD12 17: PD13 18: PD14 19: PD15	20: PF0 21: PF1 22: PF2 23: PF3	24: PF4 25: PF5 26: PF6 27: PF7	28: PA0 29: PA1 30: PA2 31: PA3	USART1 clear to send hardware flow control input.
US1_RTS	0: PA5 1: PB11 2: PB12 3: PB13	4: PB14 5: PB15 6: PC6 7: PC7	8: PC8 9: PC9 10: PC10 11: PC11	13: PD10 14: PD11 15: PD12	16: PD13 17: PD14 18: PD15 19: PF0	20: PF1 21: PF2 22: PF3 23: PF4	24: PF5 25: PF6 26: PF7 27: PA0	28: PA1 29: PA2 30: PA3 31: PA4	USART1 request to send hardware flow control output.
US1_RX	0: PA1 1: PA2 2: PA3 3: PA4	4: PA5 5: PB11 6: PB12 7: PB13	8: PB14 9: PB15 10: PC6 11: PC7	12: PC8 13: PC9 14: PC10 15: PC11	17: PD10 18: PD11 19: PD12	20: PD13 21: PD14 22: PD15 23: PF0	24: PF1 25: PF2 26: PF3 27: PF4	28: PF5 29: PF6 30: PF7 31: PA0	USART1 Asynchro- nous Receive. USART1 Synchro- nous mode Master Input / Slave Out- put (MISO).
US1_TX	0: PA0 1: PA1 2: PA2 3: PA3	4: PA4 5: PA5 6: PB11 7: PB12	8: PB13 9: PB14 10: PB15 11: PC6	12: PC7 13: PC8 14: PC9 15: PC10	16: PC11 18: PD10 19: PD11	20: PD12 21: PD13 22: PD14 23: PD15	24: PF0 25: PF1 26: PF2 27: PF3	28: PF4 29: PF5 30: PF6 31: PF7	USART1 Asynchro- nous Transmit.Also used as receive in- put in half duplex communication. USART1 Synchro- nous mode Master Output / Slave In- put (MOSI).

6.3 GPIO Pinout Overview

The GPIO pins are organized as 16-bit ports indicated by letters A through F, and the individual pins on each port is indicated by a number from 15 down to 0.

Table 6.3. GPIO Pinout

Port	Pin 15	Pin 14	Pin 13	Pin 12	Pin 11	Pin 10	Pin 9	Pin 8	Pin 7	Pin 6	Pin 5	Pin 4	Pin 3	Pin 2	Pin 1	Pin 0
Port A	-	-	-	-	-	-	-	-	-	-	PA5 (5V)	PA4 (5V)	PA3 (5V)	PA2 (5V)	PA1	PA0
Port B	PB15	PB14	PB13 (5V)	PB12 (5V)	PB11 (5V)	-	-	-	-	-	-	-	-	-	-	-
Port C	-	-	-	-	PC11 (5V)	PC10 (5V)	PC9 (5V)	PC8 (5V)	PC7 (5V)	PC6 (5V)	-	-	-	-	-	-
Port D	PD15 (5V)	PD14 (5V)	PD13 (5V)	PD12 (5V)	PD11 (5V)	PD10 (5V)	-	-	-	-	-	-	-	-	-	-
Port E	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
Port F	-	-	-	-	-	-	-	-	PF7 (5V)	PF6 (5V)	PF5 (5V)	PF4 (5V)	PF3 (5V)	PF2 (5V)	PF1 (5V)	PF0 (5V)

6.4 Analog Port (APORT)

The Analog Port (APORT) is an infrastructure used to connect chip pins with on-chip analog clients such as analog comparators, ADCs, and DACs. The APORT consists of wires, switches, and control needed to configurably implement the routes. Please see EFR32 Reference Manual for complete description.



Figure 6.2. EFR32MG1X232 APORT

Analog Module	Analog Module Channel	Shared Bus	Pin
ACMP0	APORT1XCH6	BUSAX	PC6
	APORT1XCH8		PC8
	APORT1XCH10	-	PC10
	APORT1XCH16	_	PF0
	APORT1XCH18	_	PF2
	APORT1XCH20	_	PF4
	APORT1XCH22	_	PF6
	APORT1YCH7	BUSAY	PC7
	APORT1YCH9	_	PC9
	APORT1YCH11		PC11
	APORT1YCH17	_	PF1
	APORT1YCH19		PF3
	APORT1YCH21		PF5
	APORT1YCH23		PF7
	APORT2XCH7	BUSBX	PC7
	APORT2XCH9		PC9
	APORT2XCH11		PC11
	APORT2XCH17		PF1
	APORT2XCH19		PF3
	APORT2XCH21		PF5
	APORT2XCH23		PF7
	APORT2YCH6	BUSBY	PC6
	APORT2YCH8		PC8
	APORT2YCH10		PC10
	APORT2YCH16		PF0
	APORT2YCH18	_	PF2
	APORT2YCH20	_	PF4
	APORT2YCH22		PF6
	APORT3XCH2	BUSCX	PD10
	APORT3XCH4	_	PD12
	APORT3XCH6		PD14
	APORT3XCH8		PA0
	APORT3XCH10		PA2
	APORT3XCH12		PA4
	APORT3XCH28		PB12
	APORT3XCH30	-	PB14

Table 6.4. APORT Client Map

Analog Module	Analog Module Channel	Shared Bus	Pin
ACMP1	APORT1XCH6	BUSAX	PC6
	APORT1XCH8	-	PC8
	APORT1XCH10	-	PC10
	APORT1XCH16	-	PF0
	APORT1XCH18	-	PF2
	APORT1XCH20	-	PF4
	APORT1XCH22	-	PF6
	APORT1YCH7	BUSAY	PC7
	APORT1YCH9	-	PC9
	APORT1YCH11	-	PC11
	APORT1YCH17	-	PF1
	APORT1YCH19	-	PF3
	APORT1YCH21	-	PF5
	APORT1YCH23		PF7
	APORT2XCH7	BUSBX	PC7
	APORT2XCH9		PC9
	APORT2XCH11		PC11
	APORT2XCH17		PF1
	APORT2XCH19	BUSBY	PF3
	APORT2XCH21		PF5
	APORT2XCH23		PF7
	APORT2YCH6		PC6
	APORT2YCH8		PC8
	APORT2YCH10		PC10
	APORT2YCH16		PF0
	APORT2YCH18		PF2
	APORT2YCH20		PF4
	APORT2YCH22	-	PF6
	APORT3XCH2	BUSCX	PD10
	APORT3XCH4	-	PD12
	APORT3XCH6	-	PD14
	APORT3XCH8		PA0
	APORT3XCH10		PA2
	APORT3XCH12	-	PA4
	APORT3XCH28		PB12
	APORT3XCH30		PB14
	APORT3YCH3	BUSCY	PD11
	APORT3YCH5	-	PD13

Analog Module	Analog Module Channel	Shared Bus	Pin
ADC0	APORT1XCH6	BUSAX	PC6
	APORT1XCH8	-	PC8
	APORT1XCH10	-	PC10
	APORT1XCH16	-	PF0
	APORT1XCH18	-	PF2
	APORT1XCH20	-	PF4
	APORT1XCH22	-	PF6
	APORT1YCH7	BUSAY	PC7
	APORT1YCH9	-	PC9
	APORT1YCH11	-	PC11
	APORT1YCH17	-	PF1
	APORT1YCH19	-	PF3
	APORT1YCH21	-	PF5
	APORT1YCH23		PF7
	APORT2XCH7	BUSBX	PC7
	APORT2XCH9		PC9
	APORT2XCH11		PC11
	APORT2XCH17		PF1
	APORT2XCH19		PF3
	APORT2XCH21		PF5
	APORT2XCH23		PF7
	APORT2YCH6	BUSBY	PC6
	APORT2YCH8		PC8
	APORT2YCH10		PC10
	APORT2YCH16		PF0
	APORT2YCH18		PF2
	APORT2YCH20	-	PF4
	APORT2YCH22	-	PF6
	APORT3XCH2	BUSCX	PD10
	APORT3XCH4	-	PD12
	APORT3XCH6		PD14
	APORT3XCH8		PA0
	APORT3XCH10		PA2
	APORT3XCH12		PA4
	APORT3XCH28		PB12
	APORT3XCH30		PB14
	APORT3YCH3	BUSCY	PD11
	APORT3YCH5]	PD13

Analog Module	Analog Module Channel	Shared Bus	Pin
IDAC0	APORT1XCH2	BUSCX	PD10
	APORT1XCH4		PD12
	APORT1XCH6		PD14
	APORT1XCH8		PA0
	APORT1XCH10		PA2
	APORT1XCH12		PA4
	APORT1XCH28		PB12
	APORT1XCH30		PB14
	APORT1YCH3	BUSCY	PD11
	APORT1YCH5		PD13
	APORT1YCH7		PD15
	APORT1YCH9		PA1
	APORT1YCH11		PA3
	APORT1YCH13		PA5
	APORT1YCH27		PB11
	APORT1YCH29		PB13
	APORT1YCH31		PB15

6.5 QFN48 Package Dimensions



Figure 6.3. QFN48 Package Drawing

Table 6.5. QFN48 Package Dimensions

Dimension	Min	Тур	Max	
A	0.80	0.85	0.90	
A1	0.00	0.02	0.05	
A3	0.20 REF			
b	0.18	0.25	0.30	
D	6.90	7.00	7.10	

Dimension	Min	Тур	Мах		
E	6.90	7.00	7.10		
D2	4.60	4.70	4.80		
E2	4.60	4.70	4.80		
e		0.50 BSC			
L	0.30	0.40	0.50		
К	0.20	—	_		
R	0.09	—	0.14		
ааа		0.15			
bbb		0.10			
CCC		0.10			
ddd		0.05			
eee		0.08			
fff		0.10			

Note:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.

2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.

3. This drawing conforms to the JEDEC Solid State Outline MO-220, Variation VKKD-4.

4. Recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

6.6 QFN48 PCB Land Pattern





Table 6.6. QFN48 PCB Land Pattern Dimensions

Dimension	Тур
S1	6.01
S	6.01
L1	4.70
W1	4.70
e	0.50
W	0.26

Dimension	Тур		
L	0.86		
Note:			
1. All dimensions shown are in millimeters (mm) unless otherwise noted.			
2. This Land Pattern Design is based on the IPC-7351 guidelines.			
 All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60 μm minimum, all the way around the pad. 			
4. A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.			
5. The stencil thickness should be 0.125 mm (5 mils).			

6. The ratio of stencil aperture to land pad size can be 1:1 for all perimeter pads.

- 7. A 4x4 array of 0.75 mm square openings on a 1.00 mm pitch can be used for the center ground pad.
- 8. A No-Clean, Type-3 solder paste is recommended.
- 9. The recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

6.7 QFN48 Package Marking



Figure 6.5. QFN48 Package Marking

The package marking consists of:

- PPPPPPPP The part number designation.
- TTTTTT A trace or manufacturing code. The first letter is the device revision.
- YY The last 2 digits of the assembly year.
- WW The 2-digit workweek when the device was assembled.
- # The firmware revision.

7. Revision History

7.1 Revision 0.71

2015-09-08

Revisions specific to Mighty Gecko

- Front Page: Key Features
- · Section 1. Features. Modulation Formats Supported, 2.4GHz-only devices
- Section 3.3.4 Receiver Architecture
- · Section 3.3.8 Flexible Frame Handling
- Section 3.3.17 Integrated Voltage Regulators
- · Section 4. Electrical Characteristics. Table column ordering.
- Section 4.10 RFSENSE. Correct unit.

7.2 Revision 0.7

2015-08-31

Outcome of comprehensive review cycle of EFR32BG Datasheets. Major changes span the following sections

- Section 2: Ordering Information
- Section 3.3.4: Receiver Architecture
- Section 3.3.5: Transmitter Architecture
- Section 4: Electrical Characteristics
- · Section 4.3.1: General Operating Conditions
- Section 4.4: DC-DC Converter
- Section 4.5: Current Consumption
- Section 4.9.1: RF Transmitter Characteristics for 2.4 GHz Band
- · Section 4.9.2: RF Receiver General Characteristics for 2.4 GHz Band
- · Section 4.9.3: RF Transmitter Characteristics for Bluetooth Smart in 2.4 GHz Band
- · Section 4.9.4: RF Receiver Characteristics for Bluetooth Smart in 2.4 GHz Band
- Section 4.11.1: LFXO
- Section 4.11.2: HFXO
- Section 4.12: GPIO
- Section 4.13: VMON
- Section 4.14: ADC
- Section 4.15: IDAC
- · Section 4.16: Analog Comparator
- Section 5: Application Circuits
- Section 6.5: QFNxx Package
- Section 6.7: QFNxx Package Marking

7.3 Revision 0.63

2015-07-07

Section 1. Features. correct Ultra Low Energy Timer/Counter bit width.

Section 2. Ordering information : revisions of Max TX power according to part number.

Section 3. System Summary: clarify Crypto options. Revise text desribing Transmitter Architecture and Flexible Frame Handling.

Section 4. Electrical Characteristics: revise RF performance specification tables.

7.4 Revision 0.62

2015-06-18

Revise current consumption table format.

8. Abbreviations

Table 8.1 Abbreviations on page 74 lists abbreviations used in this document.

Table 8.1. Abbreviations

Abbreviation	Description
ACP	Adjacent Channel Power
ACS	Adjacent Channel Selectivity
ADC	Analog to Digital Converter
AGC	Automatic Gain Control
ASK	Amplitude-Shift Keying
BALUN	BALanced UNbalanced (differential to single ended conversion)
BPSK	Binary Phase-Shift Keying
BT	Bandwidth Time
CMU	Clock Management Unit
CRC	Cyclic Redundancy Check
CSP	Channel Separation
CSMA-CA	Carrier Sense Multiple Access - Collision Avoidance
DAC	Digital to Analog Converter
DMA	Direct Memory Access
DSSS	Direct Sequence Spread Spectrum
ECC	Elliptic Curve Cryptography
EFR	Energy Friendly Radio
EMU	Energy Management Unit
EM	Energy Mode
ESD	Electrostatic Discharge
ESR	Equivalent Series Resistance
FEC	Forward Error Correction
FPU	Floating Point Unit
FRC	Frame Controller
FSK	Frequency-Shift Keying
GCM	Galois Counter Mode
GFSK	Gaussian Frequency-Shift Keying
IF	Intermediate Frequency
LBT	Listen Before Talk
LNA	Low Noise Amplifier
LO	Local Oscillator
MSC	Memory System Controller
MSK	Minimum-Shift Keying

Abbreviation	Description
ООК	On-Off Keying
O-QPSK	Offset Quadrature Phase-Shift Keying
PA	Power Amplifier
PRS	Peripheral Reflex System
PSK	Phase-Shift Keying
PWM	Pulse-Width Modulation
RF	Radio Frequency
RMU	Reset Management Unit
RSSI	Received Signal Strength Indicator
RTCC	Real Time Counter and Calendar
SPI	Serial Peripheral Interface
SRI	Simplified Radio Interface
ТСХО	Temperature Compensated Crystal Oscillator

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